TLV321x and TLV322x 40ns High-Speed Comparators with Rail-to-Rail Input

1 Features

- Propagation delay: 40ns
- Low supply current: 40µA per channel
- Input offset voltage: ±1mV maximum
- Internal hysteresis: 1.8mV
- Input voltage range extends 200mV beyond rails
- Power-on Reset (POR) for known start-up
- Push-pull output option (TLV32**1**x)
- Open-drain output option (TLV32**2**x)

2 Applications

- Motor drives
- Appliances
- Grid infrastructure
- Factory automation and control
- Traction inverter

3 Description

The TLV321x and TLV322x are a family of 5V single, dual and quad channel high-speed comparators with push-pull or open-drain output options. The family has an excellent speed-to-power combination with a propagation delay of 40ns and a full supply voltage range of 1.8V to 5.5V with a quiescent supply current of only 40µA per channel.

These features, along with fast response time, rail-to-rail inputs, low offset voltage and large output drive current make the family well suited for current sensing, zero-cross detection, and a variety of other applications where speed is critical.

The family also includes a Power-on Reset (POR) feature that holds the output in a known state until the minimum supply voltage has been reached to prevent output transients during system power-up and power-down.

The TLV321x have a push-pull output stage capable of sinking and sourcing large currents for symmetrical rise and fall times and quickly driving capacitive loads such as MOSFET gates.

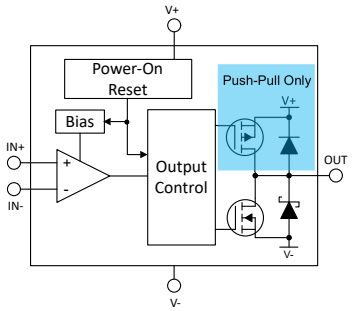
The TLV322x have an open-drain output that can be pulled-up below or beyond the supply voltage. These devices are designed for low voltage logic translators or combined ORed logic lines.

All devices are specified for operation across the expanded temperature range of –40°C to 125°C.

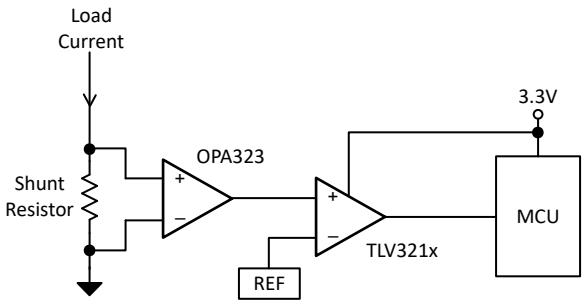
Package Information

PART NUMBER	PACKAGE (1)	PACKAGE SIZE (2)
TLV3211, TLV3221(Single)	DCK (SOT-SC70, 5)	2mm × 2.1mm
	DBV (SOT-23, 5)	2.9mm × 2.8mm
TLV3212, TLV3222 (Dual)	D (SOIC, 8)(3)	4.9mm × 6mm
	DGK (VSSOP, 8)	3.0mm × 4.9mm
	DSG (WSON, 8)(3)	2mm × 2mm
TLV3214 (Quad)	PW (TSSOP, 14)	5mm × 6.4mm
	RTE (WQFN, 16)(3)	3mm × 3mm

(1) For more information, see Section 10.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.
(3) Preview information (not Production Data).



Block Diagram



Low-Side Current Sensing

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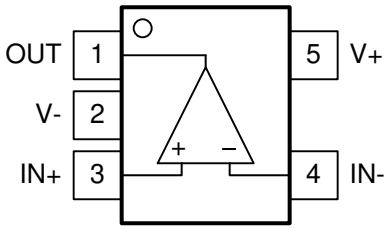
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4 Pin Configuration and Functions

4.1 Pin Configuration: TLV3211, TLV3221



DCK, DBV Packages
SC70, SOT-23-5
Top View
(North West Pinout)

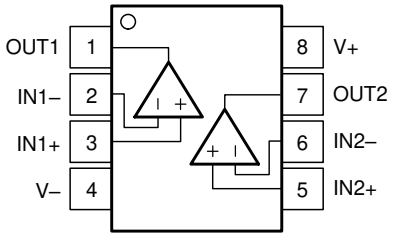
Table 4-1. Pin Functions: TLV3211, TLV3221

PIN		TYPE(1)	DESCRIPTION
NAME	NO.		
OUT	1	O	Output
V-	2	—	Negative supply voltage
IN+	3	I	Non-inverting (+) input
IN-	4	I	Inverting (-) input
V+	5	-	Positive supply voltage

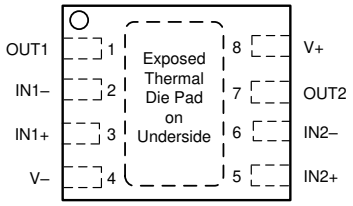
(1) I = input, O = output

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4.2 Pin Configurations: TLV3212, TLV3222



D, DGK Packages
8-Pin SOIC, VSSOP
Top View



NOTE: Connect exposed thermal pad directly to V- pin.

DSG Package
8-Pad WSON With Exposed Thermal Pad
Top View

Table 4-2. Pin Functions: TLV3212, TLV3222

PIN		TYPE(1)	DESCRIPTION
NAME	NO.		
OUT1	1	O	Output pin of the comparator 1
IN1–	2	I	Inverting input pin of comparator 1
IN1+	3	I	Noninverting input pin of comparator 1
V-	4	—	Negative supply voltage
IN2+	5	I	Noninverting input pin of comparator 2
IN2–	6	I	Inverting input pin of comparator 2
OUT2	7	O	Output pin of the comparator 2
V+	8	—	Positive supply voltage
Thermal Pad	—	—	Connect directly to V- pin

(1) I = input, O = output

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4.3 Pin Configurations: TLV3214

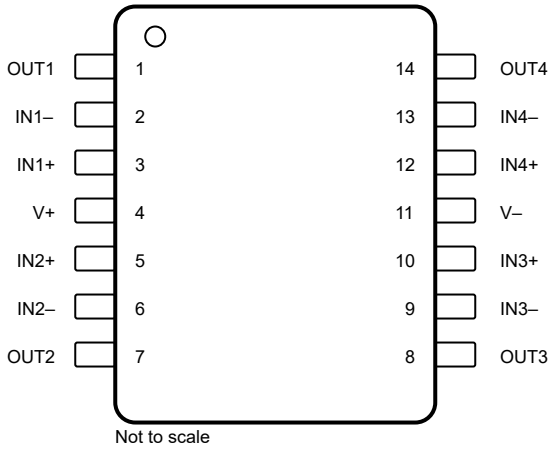
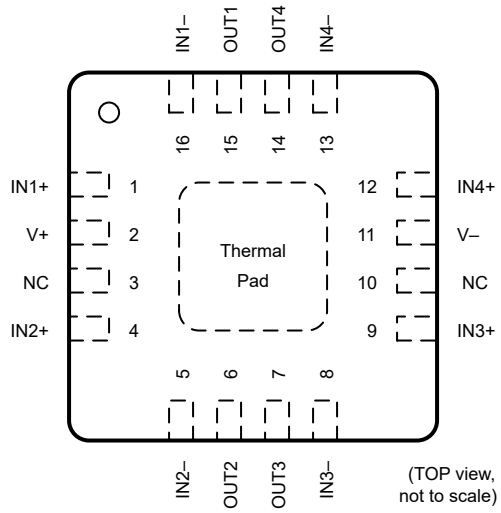


Figure 4-1. PW Package
14-Pin TSSOP
Top View



NOTE: Connect exposed thermal pad directly to V- pin.

Figure 4-2. RTE Package
16-Pin WQFN With Exposed Thermal Pad
Top View

Table 4-3. Pin Functions: TLV3214

PIN			TYPE[1]	DESCRIPTION
NAME	TSSOP	WQFN		
IN1–	2	16	I	Inverting input, channel A
IN1+	3	1	I	Noninverting input, channel A
IN2–	6	5	I	Inverting input, channel B
IN2+	5	4	I	Noninverting input, channel B
IN3–	9	8	I	Inverting input, channel C
IN3+	10	9	I	Noninverting input, channel C
IN4–	13	13	I	Inverting input, channel D
IN4+	12	12	I	Noninverting input, channel D
NC	—	3, 10	—	No internal connection
OUT1	1	15	O	Output, channel A
OUT2	7	6	O	Output, channel B
OUT3	8	7	O	Output, channel C
OUT4	14	14	O	Output, channel D
V-	11	11	—	Negative (lowest) supply or ground (for single-supply operation)
V+	4	2	—	Positive (highest) supply
Thermal Pad	—	Pad	—	Thermal Pad - Connect directly to V-

(1) I = input, O = output

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5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

	MIN	MAX	UNIT
Supply voltage V_S = (V+) - (V-)		6.5	V
Differential input voltage, VID	-6	6	V
Input pins (IN+, IN–) from (V-)(2)	– 0.5	(V+) + 0.5	V
Current into input pins (IN+, IN-)	-10	10	mA
Output (OUT) from (V-)	– 0.5	(V+) + 0.5	V
Output short-circuit current	– 100	100	mA
Output short-circuit duration		10	s
Junction temperature, T_J		150	°C
Storage temperature, T_{stg}	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* can cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods can affect device reliability.
(2) Input terminals are diode-clamped to (V–) and (V+). Input signals that can swing more than 0.5V beyond the supply rails must be current-limited to 10mA or less.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
$V_{(ESD)}$	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1000	V

(1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Supply voltage V_S = (V+) - (V-)	1.8	5.5	V
Input voltage range	(V-) - 0.2	(V+) + 0.2	V
Ambient temperature, T_A	–40	125	°C

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5.4 Thermal Information - Single

THERMAL METRIC (1)		TLV3211, TLV3221		UNIT
		DCK (SC70)	DBV (SOT-23)	
		5 PINS	5 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	222.0	203.0	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	126.2	96.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	56.1	62.4	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	29.6	32.2	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	56.0	62.0	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	–	–	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics report.

5.5 Thermal Information - Dual

THERMAL METRIC (1)		TLV3212, TLV3222			UNIT
		DGK (VSSOP)	DSG (WSON)	D (SOIC)	
		8 PINS	8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	141.7	–	132.0	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	59.9	–	69.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	78.8	–	75.2	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	6.0	–	20.3	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	78.1	–	74.6	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	–	–	–	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics report.

5.6 Thermal Information - Quad

THERMAL METRIC (1)		TLV3214		UNIT
		PW (TSSOP)	RTE (WQFN)	
		14 PINS	16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	114.8	–	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	49.9	–	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	70.7	–	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	5.8	–	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	70.0	–	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	–	–	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics report.

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5.7 Electrical Characteristics

V_S = 1.8V to 5V, V_{CM} = V_S / 2; at T_A = 25°C (unless otherwise noted). Typical values are at T_A = 25°C.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DC Input Characteristics						
V_{IO}	Input Offset Voltage	V_S = 5V, V_{CM} = V_S / 2 T_A = -40 to 125℃		±1	±6	mV
dV_{OS}/dT	Input offset voltage drift	V_S = 5V, V_{CM} = V_S / 2, T_A = -40 to 125℃		1		µV/°C
V_{HYS}	Hysteresis	V_S = 5V, V_{CM} = V_S / 2		1.8		mV
V_{HYS}	Hysteresis	V_S = 5V, V_{CM} = V_S / 2, T_A = -40 to 125℃			4	mV
V_{CM}	Common-mode voltage range		(V-) - 0.2		(V+) + 0.2	V
I_B	Input bias current	V_S = 5V, V_{CM} = V_S / 2		1	5	pA
I_B	Input bias current	V_S = 5V, V_{CM} = V_S / 2, T_A = -40 to 125℃			1200	pA
I_{OS}	Input offset current	V_S = 5V, V_{CM} = V_S / 2		0.1	2.5	pA
I_{OS}	Input offset current	V_S = 5V, V_{CM} = V_S / 2, T_A = -40 to 125℃			250	pA
C_{IN}	Input capacitance			1.5		pF
R_{DM}	Input differential mode resistance			1600		GΩ
R_{CM}	Input common mode resistance			550		GΩ
CMRR	Common-mode rejection ratio	V_{CM} = (V-) - 0.2 to (V+) + 0.2		76		dB
DC Output Characteristics						
V_{OH}	Voltage swing from (V+)	V_S = 5V, I_{Source} = 4mA (push-pull only)		135	165	mV
V_{OH}	Voltage swing from (V+)	V_S = 5V, I_{Source} = 4mA, -40 to 125C (push-pull only)			200	mV
V_{OL}	Voltage swing from (V-)	V_S = 5V, I_{Sink} = 4mA		120	160	mV
V_{OL}	Voltage swing from (V-)	V_S = 5V, I_{Sink} = 4mA, -40 to 125C			180	mV
I_{SC}	Short-circuit current	V_S = 5V, sourcing		87		mA
		V_S = 5V, sourcing, -40 to 125C			110	
I_{SC}	Short-circuit current	V_S = 5V, sinking		96		mA
		V_S = 5V, sinking, -40 to 125C			120	
I_{LKG}	Open-drain output leakage current	V_{PULLUP} = V_S (open-drain only)		50		pA
Power Supply						
I_Q	Supply current / Channel (SINGLE and DUAL)	V_S = 2.7V and 5V, no load, V_{ID} = –0.1V (Output Low), -40 to 125C		42	53	uA
I_Q	Supply current / Channel (QUAD)	V_S = 2.7V and 5V, no load, V_{ID} = –0.1V (Output Low), -40 to 125C		42	48	uA
I_Q	Supply current / Channel (SINGLE)	V_S = 2.7V and 5V, no load, V_{ID} = +0.1V (Output High), T_A = -40 to 125℃		48	60	uA
I_Q	Supply current / Channel (DUAL and QUAD)	V_S = 2.7V and 5V, no load, V_{ID} = +0.1V (Output High), T_A = -40 to 125℃		44	60	uA
$V_{POR\ (postive)}$	Power-On Reset Voltage			1.65		V
PSRR	Power Supply Rejection Ratio	V_S = 1.8V to 5.5V, no load, V_{ID} = +0.1V, T_A = -40 to 125℃		77		dB

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5.8 Switching Characteristics

For V_S = 5V, V_{CM} = V_S / 2; C_L = 15pF at T_A = 25°C (Unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PHL}	Propagation delay time, high to-low	Midpoint of input to midpoint of output, V_{OD} = 20mV		56		ns
t_{PHL}	Propagation delay time, high to-low	Midpoint of input to midpoint of output, V_{OD} = 20mV (R_P = 2.5kΩ for open-drain only)		56		ns
t_{PHL}	Propagation delay time, high to-low	Midpoint of input to midpoint of output, V_{OD} = 50mV		42		ns
t_{PHL}	Propagation delay time, high to-low	Midpoint of input to midpoint of output, V_{OD} = 50mV (R_P = 2.5kΩ for open-drain only)		42		ns
t_{PHL}	Propagation delay time, high to-low	Midpoint of input to midpoint of output, V_{OD} = 100mV		34	40	ns
t_{PHL}	Propagation delay time, high to-low	Midpoint of input to midpoint of output, V_{OD} = 100mV (R_P = 2.5kΩ for open-drain only)		34	40	ns
t_{PHL}	Propagation delay time, high to-low	Midpoint of input to midpoint of output, V_{OD} = 100mV, -40 to 125℃			50	ns
t_{PLH}	Propagation delay time, low-to high	Midpoint of input to midpoint of output, V_{OD} = 20mV (push-pull only)		54		ns
t_{PLH}	Propagation delay time, low-to high	Midpoint of input to midpoint of output, V_{OD} = 50mV (push-pull only)		39		ns
t_{PLH}	Propagation delay time, low-to high	Midpoint of input to midpoint of output, V_{OD} = 100mV (push-pull only)		32	39	ns
t_{PLH}	Propagation delay time, low-to high	Midpoint of input to midpoint of output, V_{OD} = 100mV, -40 to 125℃ (push-pull only)			50	ns
t_{PD} Skew	Propagation delay skew	Measured as absolute value of the difference between tPDLH and tPDHL, V_{OD} = 100mV (push-pull only)		3.5		ns
t_{PD} ch-ch skew	Channel-to-channel propagation delay skew (dual and quad only)	V_{CM} = V_S/2, $V_{OVERDRIVE}$ = $V_{UNDERDRIVE}$ = 50mV, 10MHz Squarewave		1.3		ns
f_{TOGGLE}	Input toggle frequency	V_{IN} = 200mV_{PP} Sine Wave, When output high reaches 90% of (V+) - (V-) or output low reaches 10% of (V+) - (V-)		12		MHz
t_R	Rise time	Measured from 20% to 80% (for push-pull only)		1.5		ns
t_F	Fall time	Measured from 20% to 80%		1.5		ns
t_{ON}	Power-up time	During power on, (V+) must exceed 1.65V for 32µs before the output reflects the input		32		µs

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5.9 Typical Characteristics

T_A = 25°C, V_S = 5V, C_L = 15pF, V_{CM} = V_S/2V, $V_{UNDERDRIVE}$ = 50mV, $V_{OVERDRIVE}$ = 50mV unless otherwise noted.

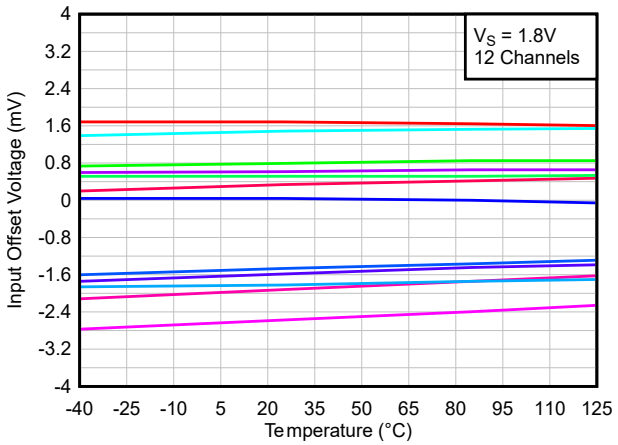


Figure 5-1. Offset Voltage vs. Temperature, 1.8V

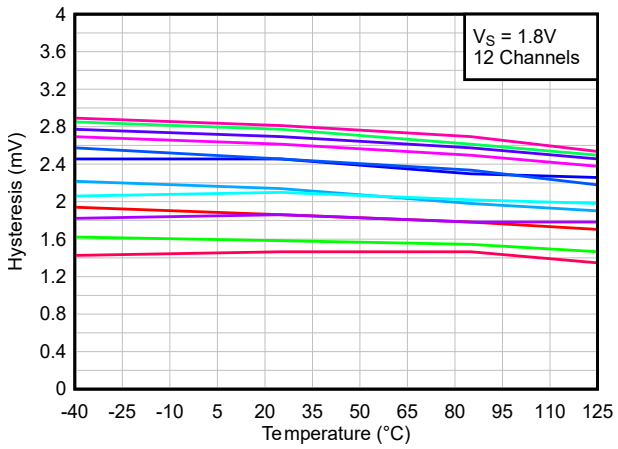


Figure 5-2. Hysteresis vs. Temperature, 1.8V

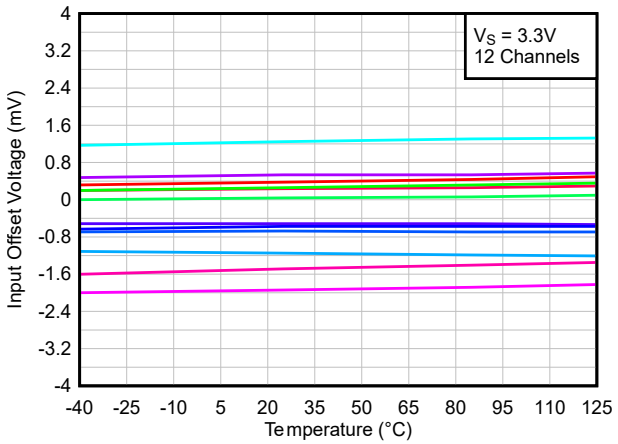


Figure 5-3. Offset Voltage vs. Temperature, 3.3V

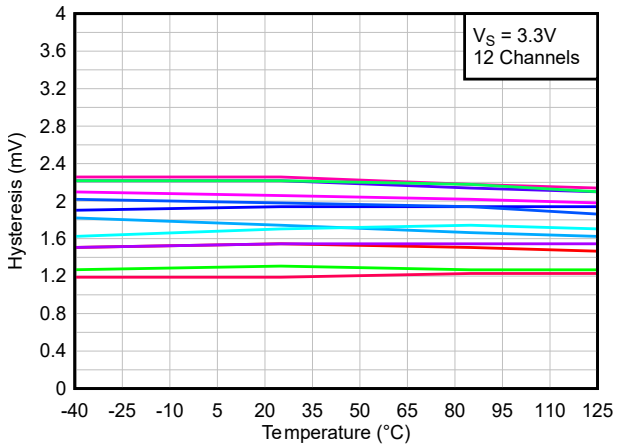


Figure 5-4. Hysteresis vs. Temperature, 3.3V

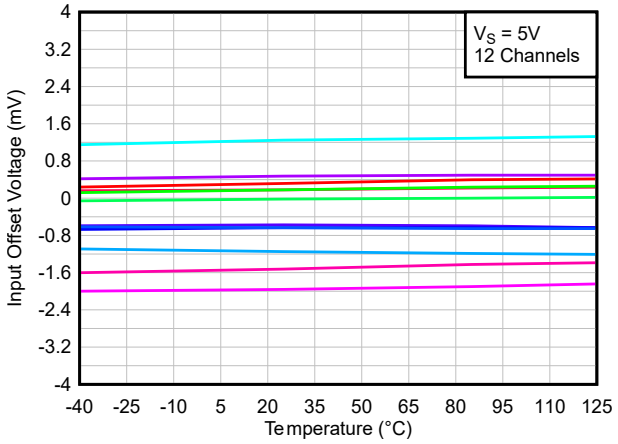


Figure 5-5. Offset Voltage vs. Temperature, 5V

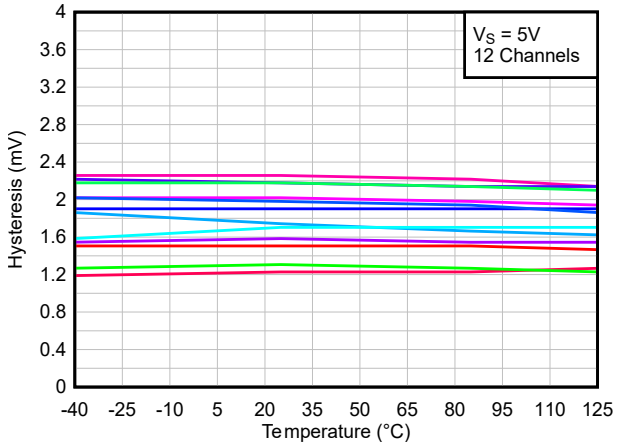


Figure 5-6. Hysteresis vs. Temperature, 5V

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5.9 Typical Characteristics (continued)

T_A = 25°C, V_S = 5V, C_L = 15pF, V_{CM} = V_S/2V, $V_{UNDERDRIVE}$ = 50mV, $V_{OVERDRIVE}$ = 50mV unless otherwise noted.

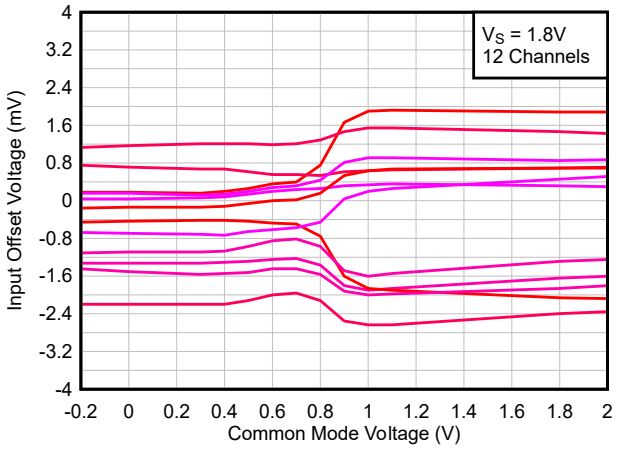


Figure 5-7. Offset Voltage vs. Common-Mode, 1.8V

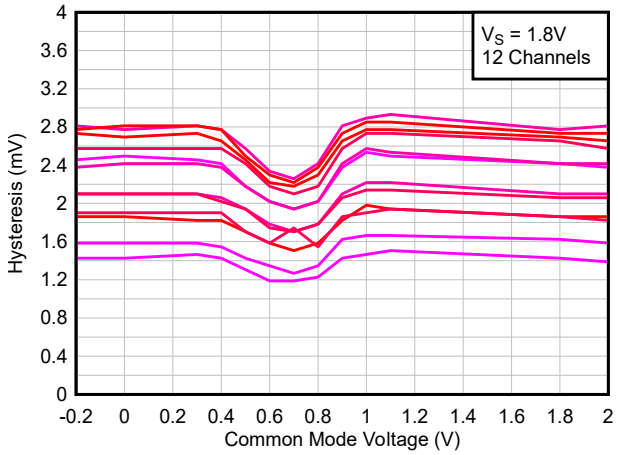


Figure 5-8. Hysteresis vs. Common-Mode, 1.8V

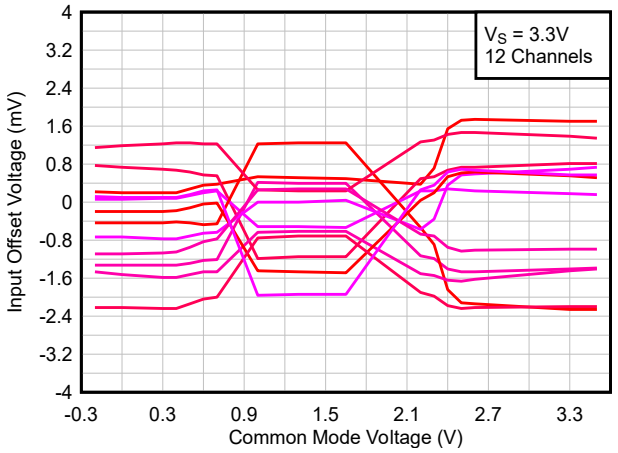


Figure 5-9. Offset vs. Common-Mode, 3.3V

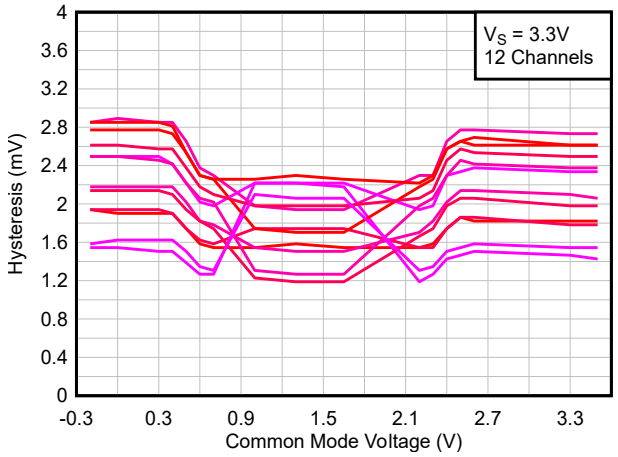


Figure 5-10. Hysteresis vs. Common-Mode, 3.3V

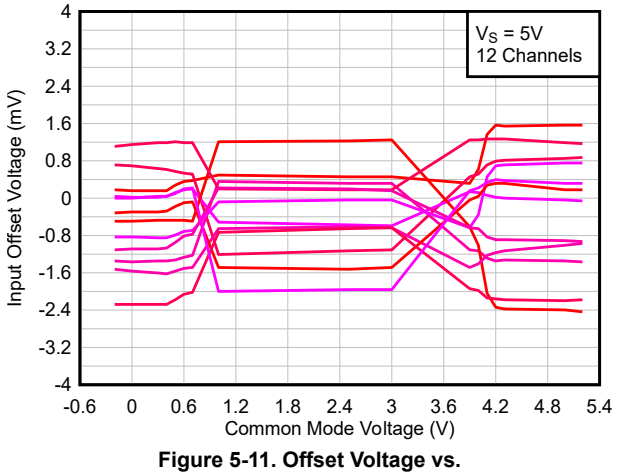


Figure 5-11. Offset Voltage vs. Common-Mode, 5V

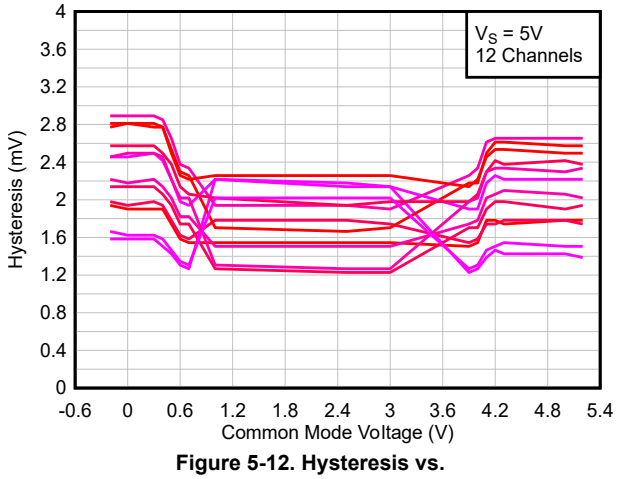


Figure 5-12. Hysteresis vs. Common-Mode, 5V

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5.9 Typical Characteristics (continued)

T_A = 25°C, V_S = 5V, C_L = 15pF, V_{CM} = V_S/2V, $V_{UNDERDRIVE}$ = 50mV, $V_{OVERDRIVE}$ = 50mV unless otherwise noted.

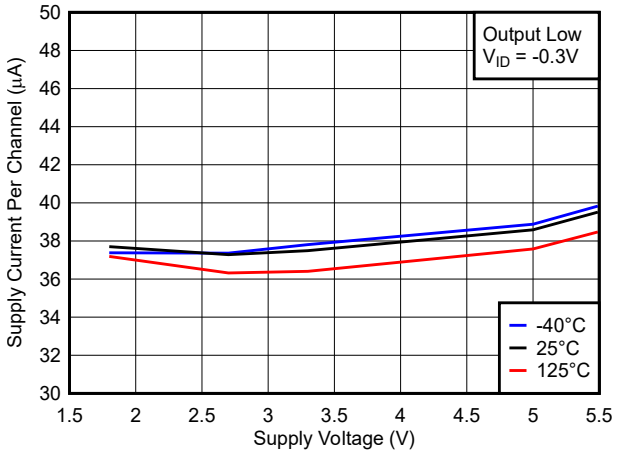


Figure 5-13. Supply Current vs. Supply Voltage (Output Low)

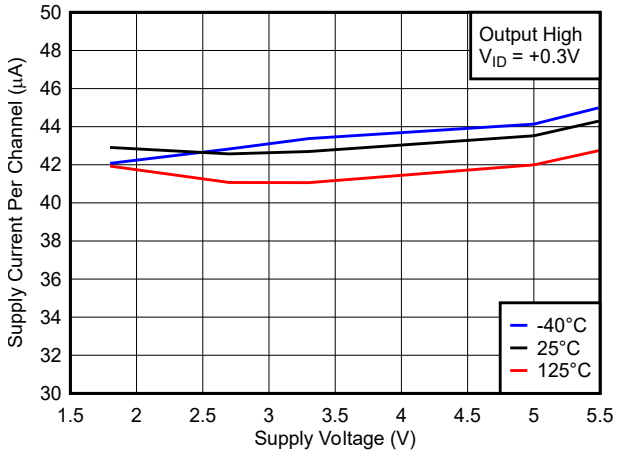


Figure 5-14. Supply Current vs. Supply Voltage (Output High)

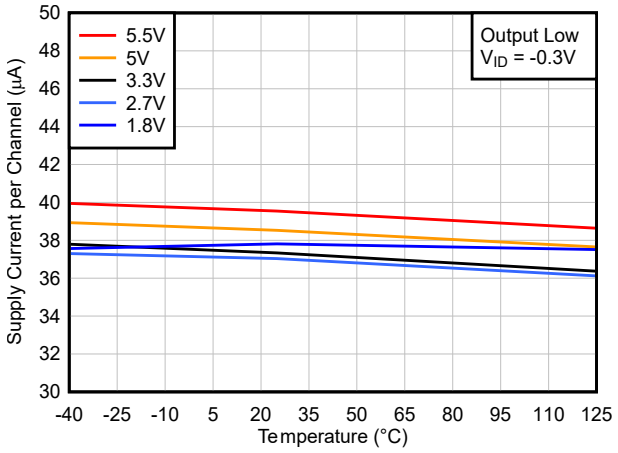


Figure 5-15. Supply Current vs. Temperature (Output Low)

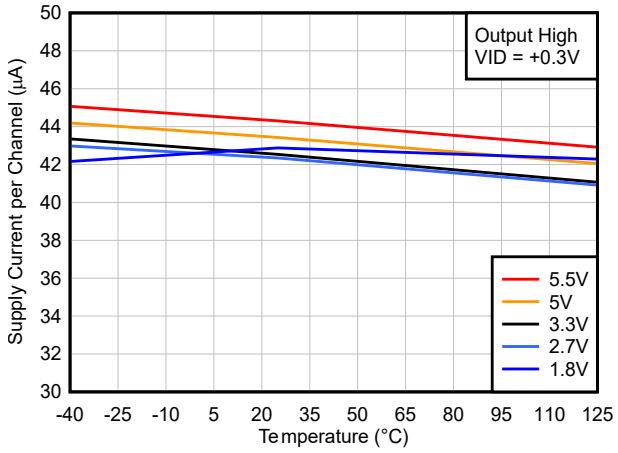


Figure 5-16. Supply Current vs. Temperature (Output High)

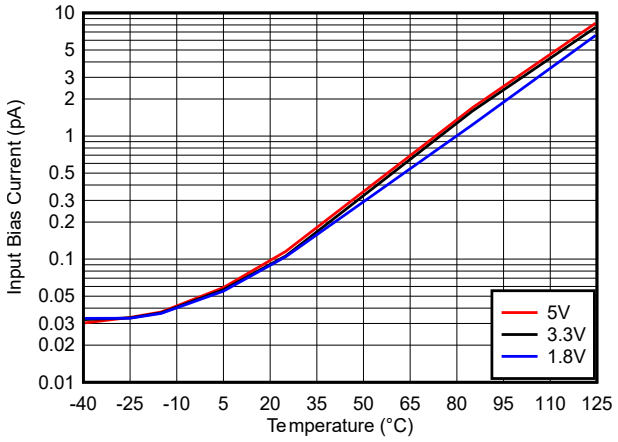


Figure 5-17. Input Bias Current vs. Temperature

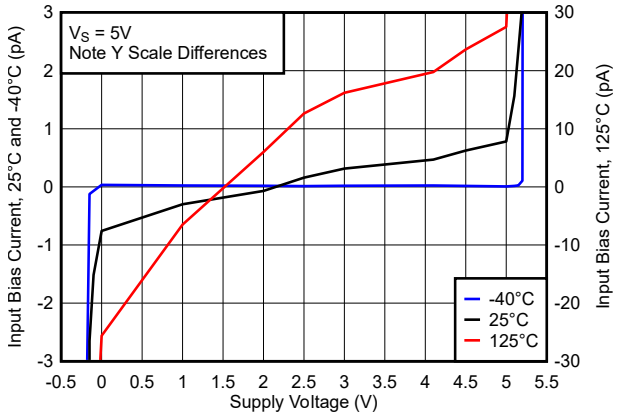


Figure 5-18. Input Bias Current vs. Common-Mode, 5V

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5.9 Typical Characteristics (continued)

T_A = 25°C, V_S = 5V, C_L = 15pF, V_{CM} = V_S/2V, $V_{UNDERDRIVE}$ = 50mV, $V_{OVERDRIVE}$ = 50mV unless otherwise noted.

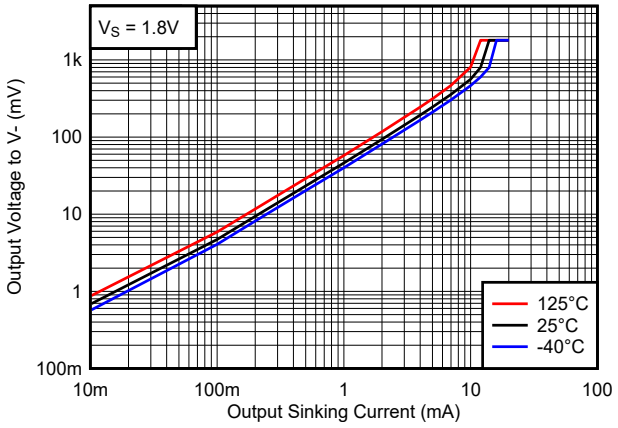


Figure 5-19. Output Voltage vs. Output Sinking Current, 1.8V

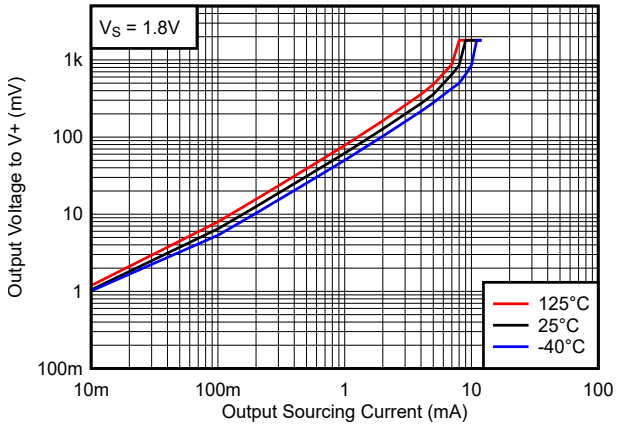


Figure 5-20. Output Voltage vs. Output Sourcing Current (Push-Pull Only), 1.8V

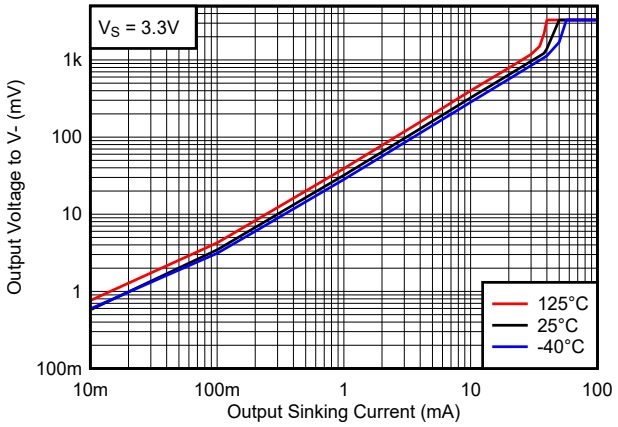


Figure 5-21. Output Voltage vs. Output Sinking Current, 3.3V

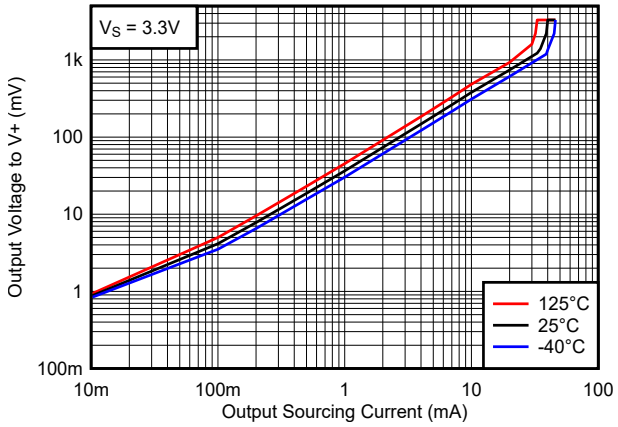


Figure 5-22. Output Voltage vs. Output Sourcing Current (Push-Pull Only), 3.3V

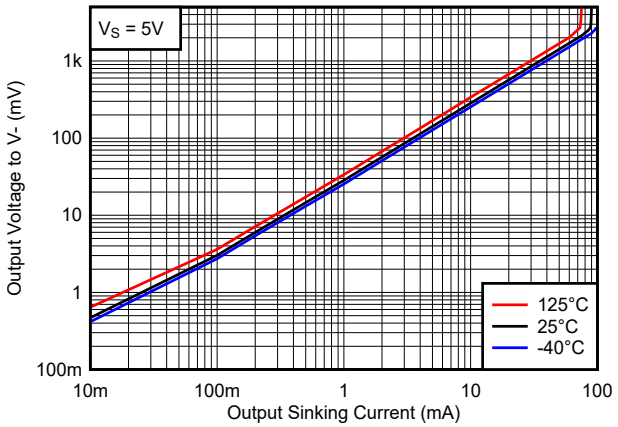


Figure 5-23. Output Voltage vs. Output Sinking Current, 5V

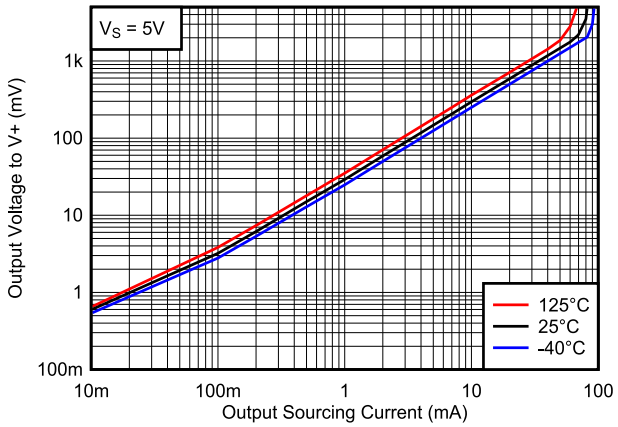


Figure 5-24. Output Voltage vs. Output Sourcing Current (Push-Pull Only), 5V

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5.9 Typical Characteristics (continued)

T_A = 25°C, V_S = 5V, C_L = 15pF, V_{CM} = V_S/2V, $V_{UNDERDRIVE}$ = 50mV, $V_{OVERDRIVE}$ = 50mV unless otherwise noted.

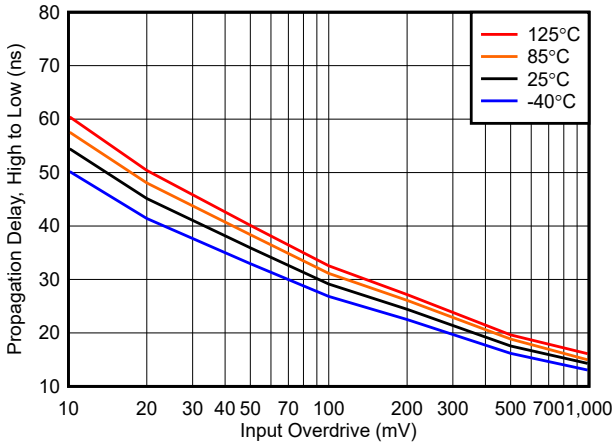


Figure 5-25. Propagation Delay, High to Low vs. Overdrive at 1.8V

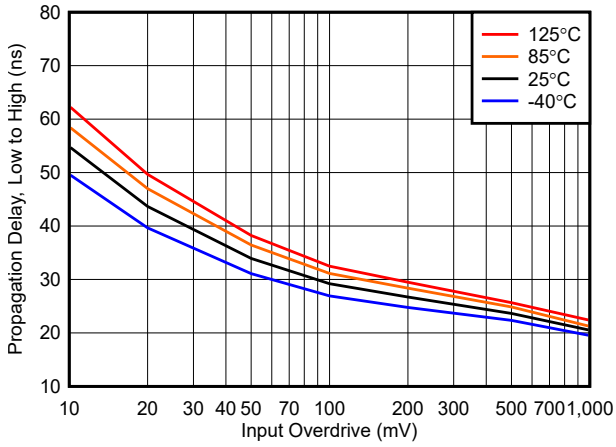


Figure 5-26. Propagation Delay, Low to High vs. Overdrive at 1.8V

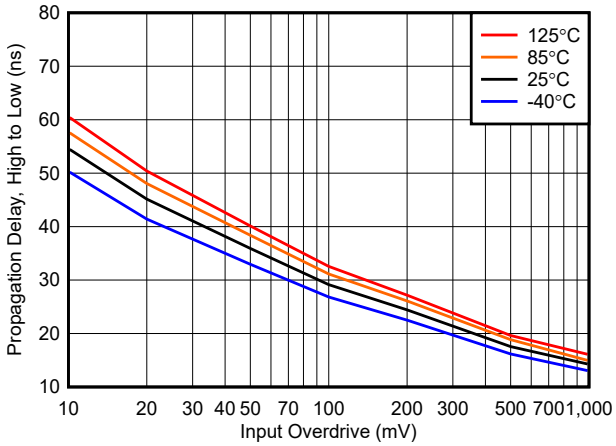


Figure 5-27. Propagation Delay, High to Low vs. Overdrive at 3.3V

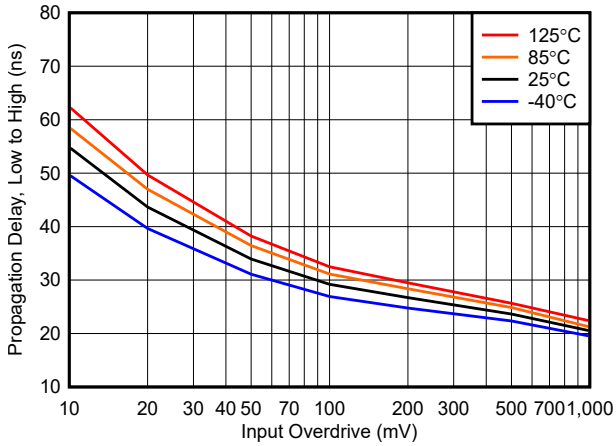


Figure 5-28. Propagation Delay, Low to High vs. Overdrive at 3.3V

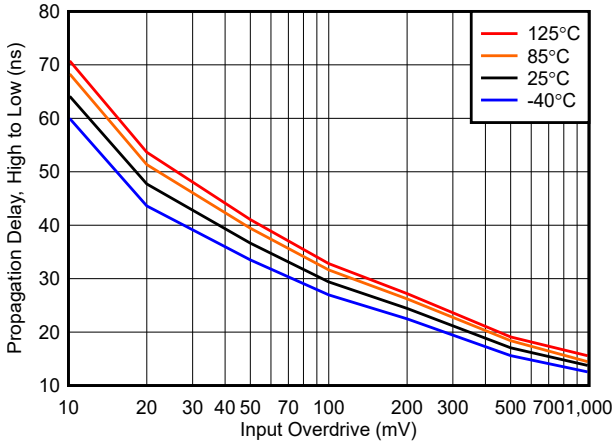


Figure 5-29. Propagation Delay, High to Low vs. Overdrive at 5V

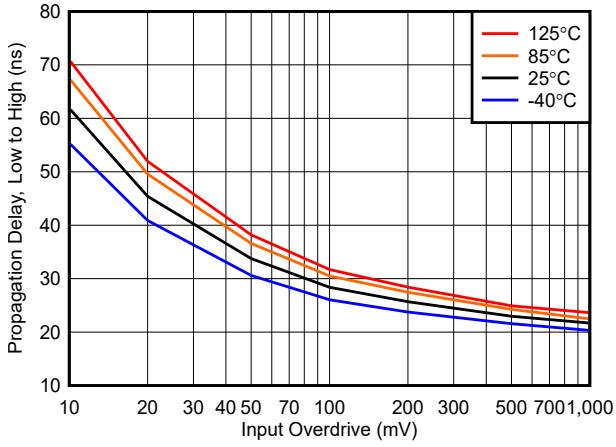


Figure 5-30. Propagation Delay, Low to High vs. Overdrive at 5V

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5.9 Typical Characteristics (continued)

T_A = 25°C, V_S = 5V, C_L = 15pF, V_{CM} = V_S/2V, $V_{UNDERDRIVE}$ = 50mV, $V_{OVERDRIVE}$ = 50mV unless otherwise noted.

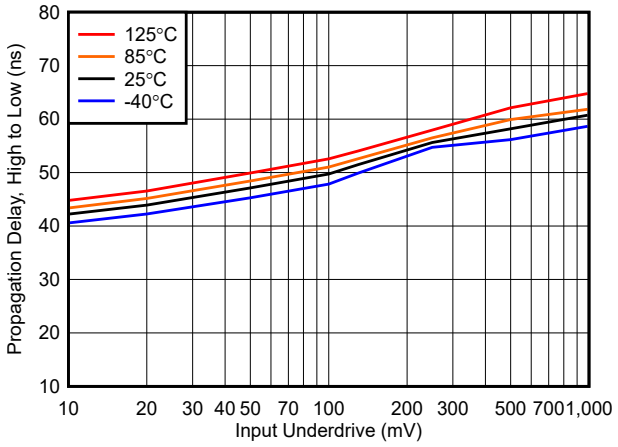


Figure 5-31. Propagation Delay, High to Low vs. Underdrive at 1.8V

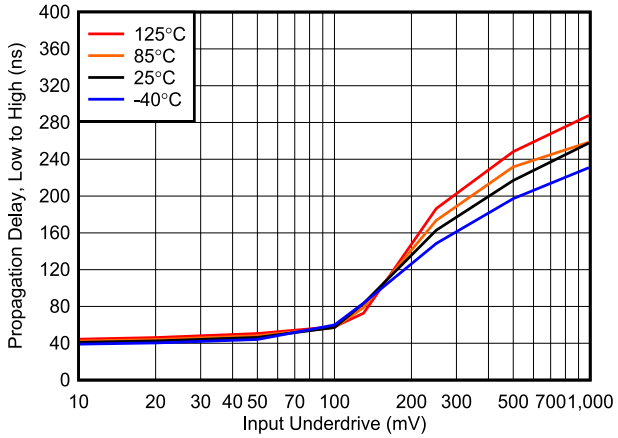


Figure 5-32. Propagation Delay, Low to High vs. Underdrive at 1.8V

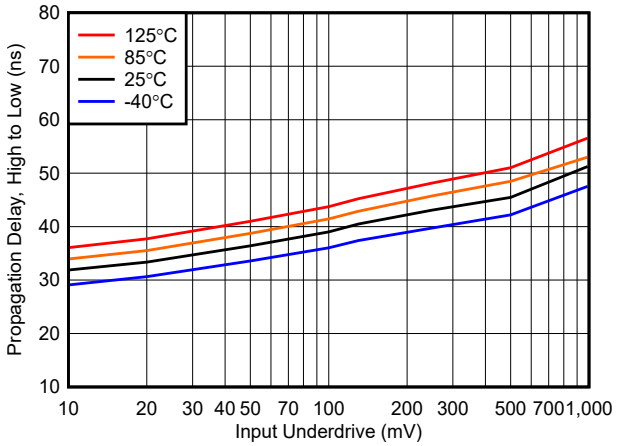


Figure 5-33. Propagation Delay, High to Low vs. Underdrive at 3.3V

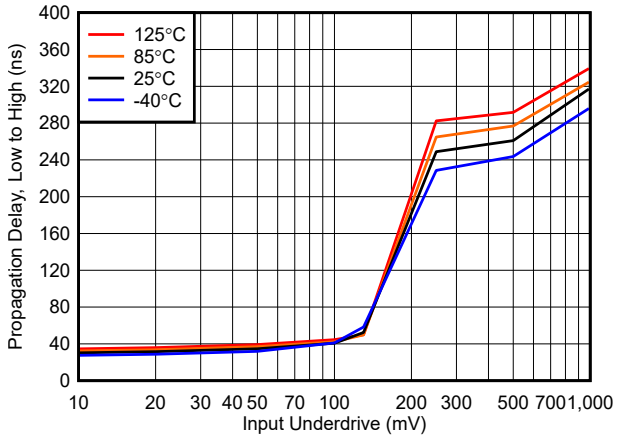


Figure 5-34. Propagation Delay, Low to High vs. Underdrive at 3.3V

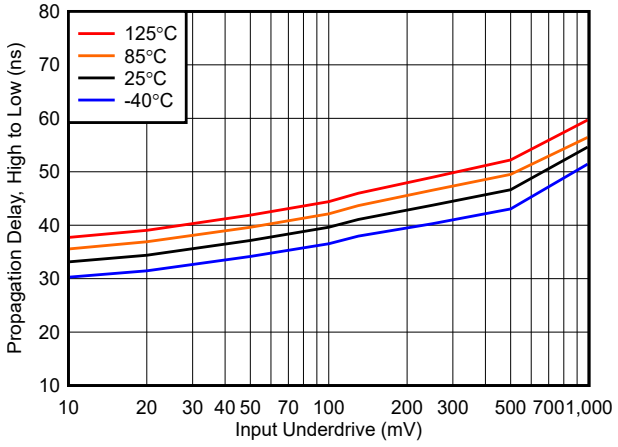


Figure 5-35. Propagation Delay, High to Low vs. Underdrive at 5V

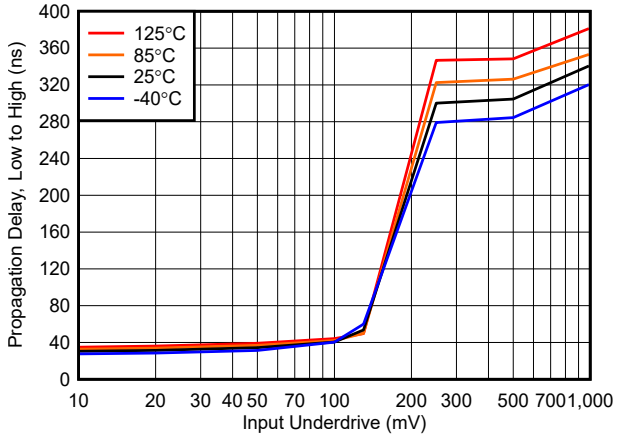


Figure 5-36. Propagation Delay, Low to High vs. Underdrive at 5V

5.9 Typical Characteristics (continued)

T_A = 25°C, V_S = 5V, C_L = 15pF, V_{CM} = V_S/2V, $V_{UNDERDRIVE}$ = 50mV, $V_{OVERDRIVE}$ = 50mV unless otherwise noted.

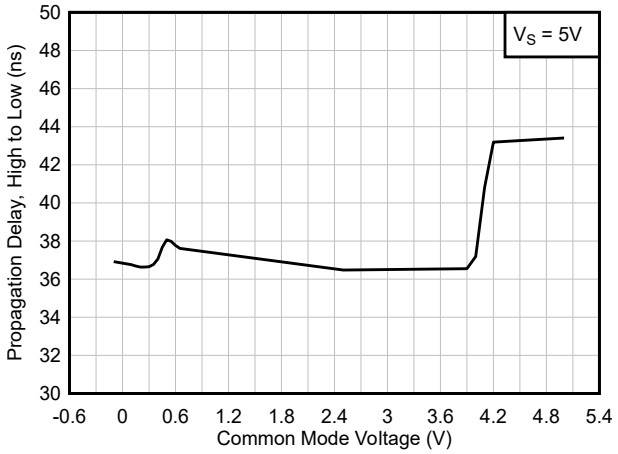


Figure 5-37. Propagation Delay, High to Low vs. Common Mode at 5V

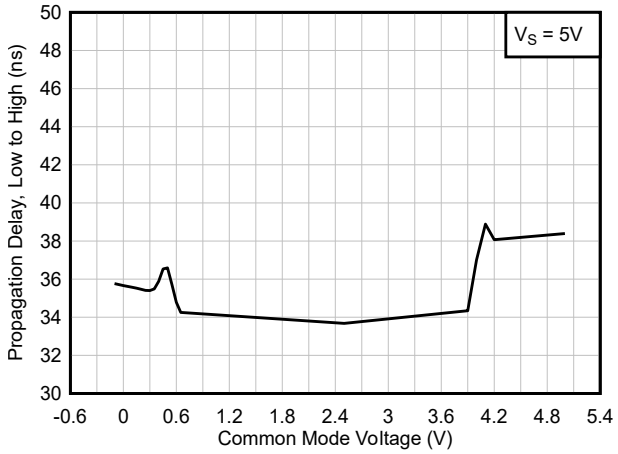


Figure 5-38. Propagation Delay, Low to High vs. Common Mode at 5V

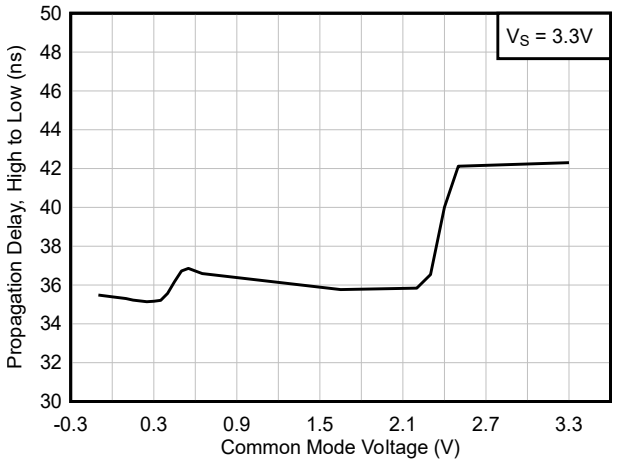


Figure 5-39. Propagation Delay, High to Low vs. Common Mode at 3.3V

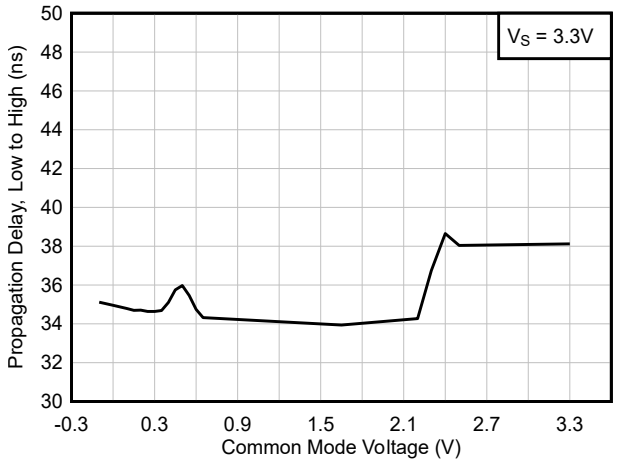


Figure 5-40. Propagation Delay, Low to High vs.Common Mode at 3.3V

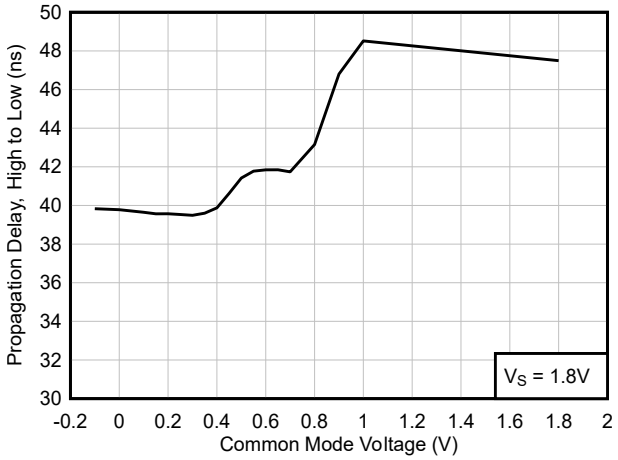


Figure 5-41. Propagation Delay, High to Low vs. Common Mode at 1.8V

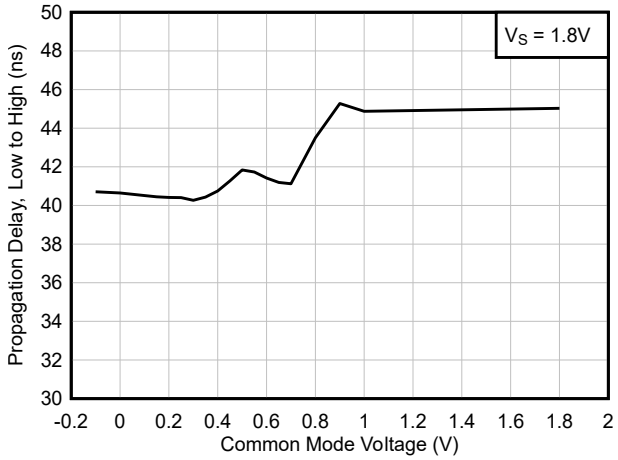


Figure 5-42. Propagation Delay, Low to High vs. Common Mode at 1.8V

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5.9 Typical Characteristics (continued)

T_A = 25°C, V_S = 5V, C_L = 15pF, V_{CM} = V_S/2V, $V_{UNDERDRIVE}$ = 50mV, $V_{OVERDRIVE}$ = 50mV unless otherwise noted.

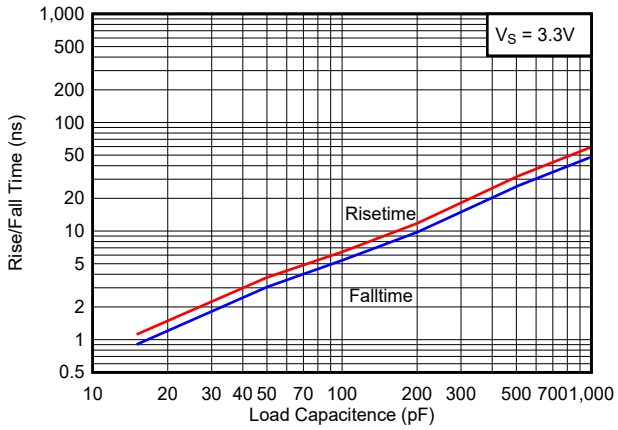


Figure 5-43. Rise and Fall Times vs. Capacitive Load

6 Detailed Description

6.1 Overview

The TLV321x devices are 40ns comparators with push-pull output.

6.2 Functional Block Diagrams

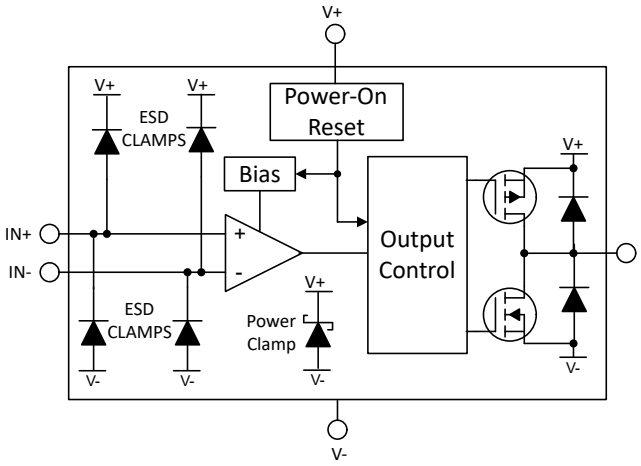


Figure 6-1. TLV321x Push-Pull Block Diagram

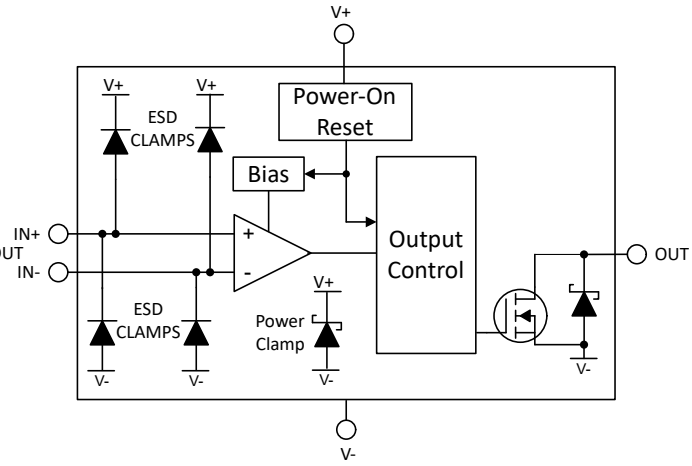


Figure 6-2. TLV322x Open-Drain Block Diagram

6.3 Feature Description

The TLV321/2x consumes only 40uA per channel with 40ns of propagation delay, detecting fast voltage and current transients while maintaining low power consumption.

The TLV321/2x family has two output options:

The TLV321x has a **push-pull** (sink-source) output.

The TLV322x has a **open-drain** (sink only) output, capable of being pulled-up to any voltage up to 5.5V, independent of comparator supply voltage.

6.4 Device Functional Modes

6.4.1 Inputs

The TLV32xx input voltage range extends from 200mV below V- to 200mV above V+. The differential input voltage (V_{ID}) can be any voltage within these limits. No phase-inversion of the comparator output occurs when the input voltages stay within the specified range.

The Rail-to-Rail input does have an ESD clamp to the V+ supply line and therefore the input voltage must not exceed the supply voltages by more than 200mV. TI does not recommend applying signals to the inputs with no supply voltage.

Limit the current to 10mA or less. TI recommends adding a resistance in series with the inputs to limit current during transients or faults. Any resistive voltage dividers or networs on the input can be part of this series resistance.

6.4.1.1 Unused Inputs

If a channel is not to be used, DO NOT tie the inputs together. Due to the high equivalent bandwidth and low offset voltage, tying the inputs directly together can cause high frequency chatter as the device triggers on it's own internal wideband noise. Instead, the inputs must be tied to any available voltage that resides within the specified input voltage range and provides a minimum of 50mV differential voltage. For example, one input can

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be grounded and the other input connected to a reference voltage, or even V+ (as long as the input is directly connected to the V+ pin to avoid transients).

6.4.2 Internal Hysteresis

The TLV32xx family contains 1.8mV of internal hysteresis.

The device hysteresis transfer curve is shown below. This curve is a function of three components: V_{TH}, V_{OS}, and V_{HYST}:

- V_{TH} is the actual set voltage or threshold trip voltage.
- V_{OS} is the internal offset voltage between V_{IN+} and $V_{IN–}$. This voltage is added to V_{TH} to form the actual trip point at which the comparator must respond to change output states.
- V_{HYST} is the internal hysteresis (or trip window) that is designed to reduce comparator sensitivity to noise.

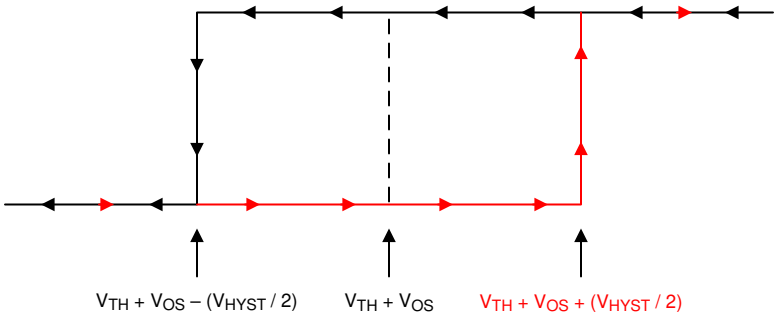


Figure 6-3. Hysteresis Transfer Curve

6.4.3 Outputs

The TLV321/2x family is available in both Push-Pull and Open-Drain output options.

The output must be treated as a high speed digital device and proper high-speed digital PCB layout and routing techniques are recommended.

6.4.3.1 TLV321x Push-Pull Output

The TLV321x features a push-pull output stage capable of both sinking and sourcing current. This allows quickly and symetrically driving loads such as MOSFET gates, as well as eliminating the need for a power-wasting external pull-up resistor. The push-pull output must never be connected to another output.

Directly shorting the output to the opposite supply rail (V+ when output "low" or V- when output "High") can result in thermal runaway and eventual device destruction. If output shorts are possible, a series current limiting resistor is recommended to limit the power dissipation.

Unused push-pull outputs must be left floating, and never tied to a supply, ground, or another output.

6.4.3.2 TLV322x Open Drain Output

The TLV322x features an open-drain (also commonly called open collector) sinking-only output stage enabling the output logic levels to be pulled up to an external voltage from 0V up to 5.5V, independent of the comparator supply voltage (V+). The open-drain output allows logical OR'ing of multiple open drain outputs and logic level translation.

TI recommends setting the pull-up resistor current to between 100uA and 1mA. Lower value pull-up resistor values can help increase the rising edge rise-time, but at the expense of increasing V_{OL} and higher power dissipation. The rise-time is dependent on the time constant of the total pull-up resistance and total load capacitance. Large value pull-up resistors (>1MΩ) creates an exponential rising edge due to the output RC time constant and increase the rise-time.

Directly shorting the output to a voltage source can result in thermal runaway and eventual device destruction. If output shorts are possible, a series current limiting resistor is recommended to limit the power dissipation.

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Unused open drain outputs can be left floating, or can be tied to the V- pin if floating pins are not desired.

6.4.4 ESD Protection

The inputs and outputs incorporate internal ESD protection circuits to (V+) and (V-).

Voltages on the inputs are limited to 0.2V beyond the rails. If the inputs are to be connected to a low impedance source, such as a power supply or buffered reference line, TI recommends adding a current-limiting resistor in series with the input to limit any transient currents if the clamps conduct. Limit the current to 10mA or less.

6.4.5 Power-On Reset (POR)

The TLV321x devices have an internal Power-on-Reset (POR) circuit for known start-up conditions. While the power supply (V+) is ramping up, the POR circuitry is activated for up to 32us after the V_{POR} of 1.65V is crossed. When the supply voltage is equal to or greater than the minimum supply voltage, and after the delay period, the comparator output reflects the state of the differential input (V_{ID}).

The output is held low during the POR period (t_{on}). This is true for both the Open-Drain and Push-Pull output options.

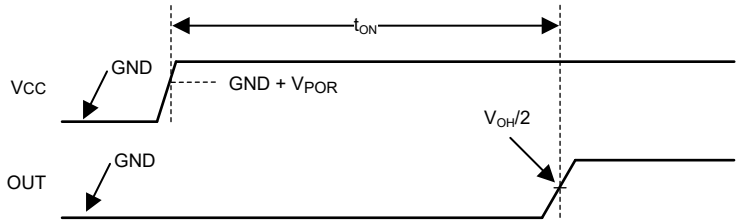


Figure 6-4. Power-On Reset Timing Diagram

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7 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

7.1 Application Information

7.1.1 Basic Comparator Definitions

7.1.1.1 Operation

The basic comparator compares the input voltage (V_{IN}) on one input to a reference voltage (V_{REF}) on the other input. In the Figure 7-1 example below, if V_{IN} is less than V_{REF}, the output voltage (V_O) is logic low (V_{OL}). If V_{IN} is greater than V_{REF}, the output voltage (V_O) is at logic high (V_{OH}). Table 7-1 summarizes the output conditions. The output logic can be inverted by simply swapping the input pins.

Table 7-1. Output Conditions

INPUTS CONDITION	OUTPUT
IN+ > IN-	HIGH (V_{OH})
IN+ = IN-	Indeterminate (chatters - see Hysteresis)
IN+ < IN-	LOW (V_{OL})

7.1.1.2 Propagation Delay

There is a delay between from when the input crosses the reference voltage and the output responds. This is called the Propagation Delay. Propagation delay can be different between high-to low and low-to-high input transitions. This is shown as t_{pLH} and t_{pHL} in Figure 7-1 and is measured from the mid-point of the input to the midpoint of the output.

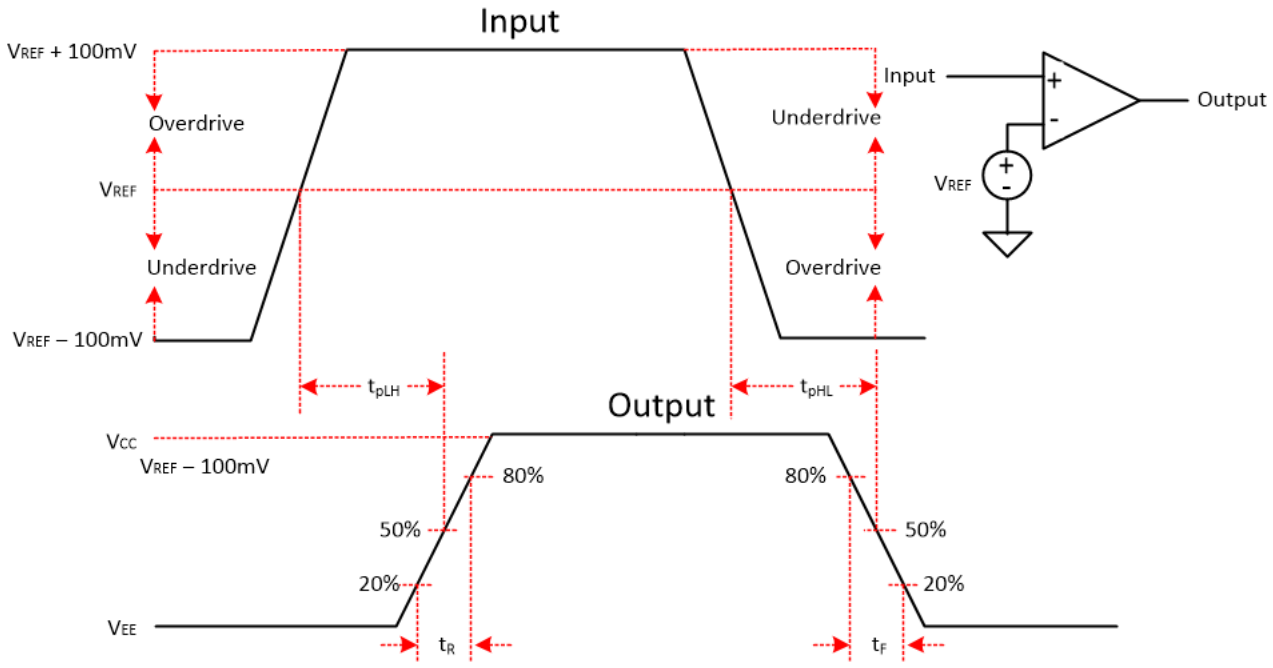


Figure 7-1. Comparator Timing Diagram

7.1.1.3 Overdrive Voltage

The overdrive voltage, V_{OD}, is the amount of input voltage beyond the reference voltage (and not the total input peak-to-peak voltage). The overdrive voltage can influence the propagation delay (t_p). The smaller the overdrive voltage, the longer the propagation delay, particularly when <100mV. If the fastest speeds are desired, apply the highest amount of overdrive possible.

The risetime (t_r) and falltime (t_f) is the time from the 20% and 80% points of the output waveform.

7.1.2 External Hysteresis

The basic comparator configuration can produce a noisy "chatter" output if the applied differential input voltage is near the comparator offset voltage. This typically occurs when the input signal is moving very slowly across the switching threshold of the comparator. This problem can be prevented by adding external hysteresis to the comparator.

Since the TLV321x devices only have 1.8mV of internal hysteresis, external hysteresis can be applied in the form of a positive feedback loop that adjusts the trip point of the comparator depending on the current output state. External hysteresis adds to the internal hysteresis.

The hysteresis transfer curve is shown in Figure 7-2. This curve is a function of three components: V_{TH}, V_{OS}, and V_{HYST}:

- V_{TH} is the actual set voltage or threshold trip voltage.
- V_{OS} is the internal offset voltage between V_{IN+} and $V_{IN–}$. This voltage is added to V_{TH} to form the actual trip point at which the comparator must respond to change output states.
- V_{HYST} is the hysteresis (or trip window) that is designed to reduce comparator sensitivity to noise.

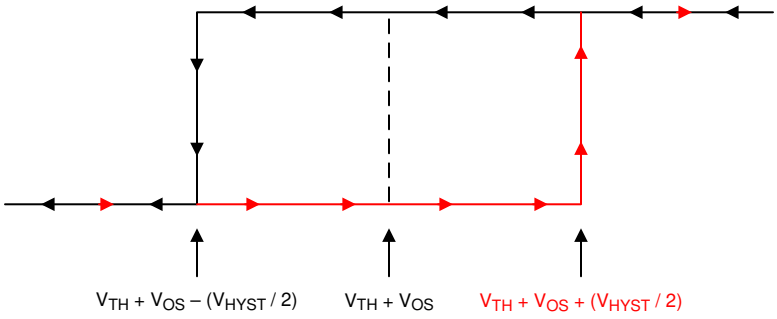


Figure 7-2. Hysteresis Transfer Curve

For more information, please see the *Comparator with and without hysteresis circuit* aplication note.

7.1.2.1 Inverting Comparator With Hysteresis

The inverting comparator with hysteresis requires a three-resistor network that is referenced to the comparator supply voltage (V_{CC}), as shown in Figure 7-3.

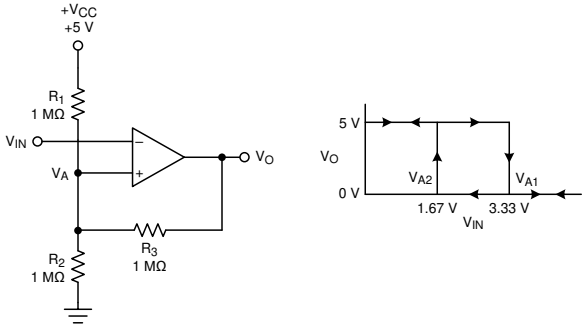


Figure 7-3. TLV321x in an Inverting Configuration With Hysteresis

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The equivalent resistor networks when the output is high and low are shown in Figure 7-3.

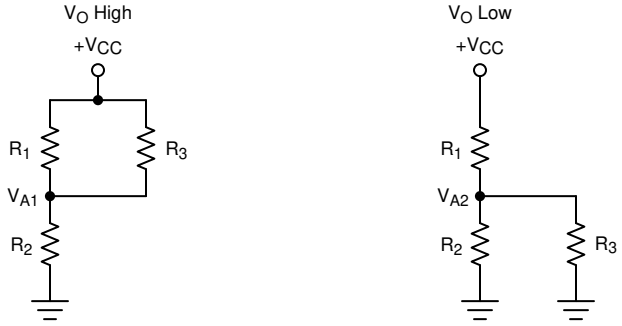


Figure 7-4. Inverting Configuration Resistor Equivalent Networks

When V_{IN} is less than V_A, the output voltage is high (for simplicity, assume V_O switches as high as V_{CC}). The three network resistors can be represented as R1 || R3 in series with R2, as shown in Figure 7-4.

Equation 1 below defines the high-to-low trip voltage (V_{A1}).

$$V_{A1} = V_{CC} \times \frac{R2}{(R1 \parallel R3) + R2} \tag{1}$$

When V_{IN} is greater than V_A, the output voltage is low. In this case, the three network resistors can be presented as R2 || R3 in series with R1, as shown in Equation 2.

Use Equation 2 to define the low to high trip voltage (V_{A2}).

$$V_{A2} = V_{CC} \times \frac{R2 \parallel R3}{R1 + (R2 \parallel R3)} \tag{2}$$

Equation 3 defines the total hysteresis provided by the network.

$$\Delta V_A = V_{A1} - V_{A2} \tag{3}$$

7.1.2.2 Non-Inverting Comparator With Hysteresis

A non-inverting comparator with hysteresis requires a two-resistor network and a voltage reference (V_{REF}) at the inverting input, as shown in Figure 7-5,

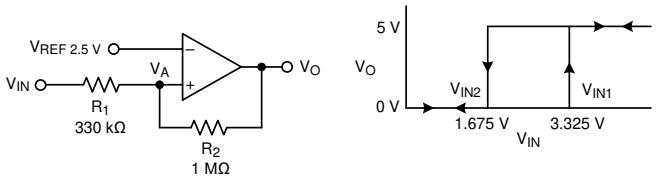


Figure 7-5. TLV321x in a Non-Inverting Configuration With Hysteresis

The equivalent resistor networks when the output is high and low are shown in Figure 7-6.

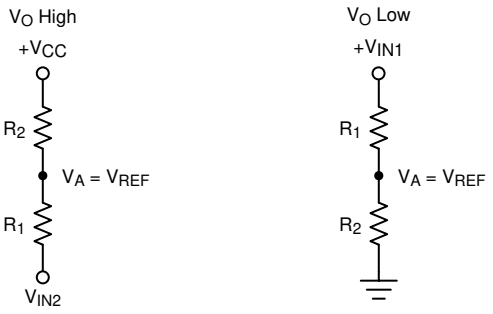


Figure 7-6. Non-Inverting Configuration Resistor Networks

When V_{IN} is less than V_{REF}, the output is low. For the output to switch from low to high, V_{IN} must rise above the V_{IN1} threshold. Use Equation 4 to calculate V_{IN1}.

$$V_{IN1} = R1 \times \frac{V_{REF}}{R2} + V_{REF} \tag{4}$$

When V_{IN} is greater than V_{REF}, the output is high. For the comparator to switch back to a low state, V_{IN} must drop below V_{IN2}. Use Equation 5 to calculate V_{IN2}.

$$V_{IN2} = \frac{V_{REF}\,(R1 + R2) - V_{CC} \times R1}{R2} \tag{5}$$

The hysteresis of this circuit is the difference between V_{IN1} and V_{IN2}, as shown in Equation 6.

$$\Delta V_{IN} = V_{CC} \times \frac{R1}{R2} \tag{6}$$

For more information, please see *Inverting comparator with hysteresis circuit* and *Non-Inverting Comparator With Hysteresis Circuit* application notes.

7.2 Typical Applications

7.2.1 Low-Side Current Sensing

Figure 7-7 shows a simple low-side current sensing circuit using an amplifier and a high-speed comparator. The amplifier is used to amplify the voltage drop across the shunt resistor. When the voltage at the output reaches the critical over-current threshold, the comparator output changes state.

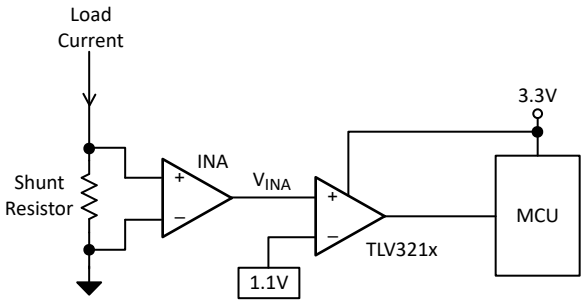


Figure 7-7. Current Sensing

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7.2.1.1 Design Requirements

For this design, follow these design requirements:

- Alert (logic high output) when the amplifier output is greater than 1.1V
- Alert signal is active high
- Operate from a 3.3V power supply

7.2.1.2 Detailed Design Procedure

Configure the circuit as shown in Figure 7-7.

7.2.1.3 Application Curve

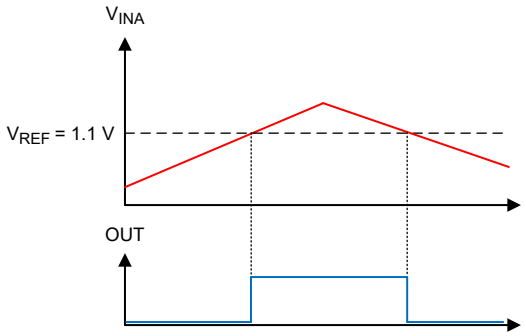


Figure 7-8. Overcurrent Results

7.3 Power Supply Recommendations

Due to the fast output edges, bypass capacitors are critical on the supply pin to prevent supply ringing and false triggers and oscillations. Bypass the supply directly at *each* device with a low ESR 0.1µF ceramic bypass capacitor directly between the (V+) pin and ground pins. Narrow peak currents are drawn during the output transition time, particularly for the push-pull output device. These narrow pulses can cause un-bypassed supply lines and poor grounds to ring, possibly causing variation that can eat into the input voltage range and create an inaccurate comparison or even oscillations.

The device can be powered from both "split" supplies ((V+) &(V-)), or "single" supplies ((V+) and GND), with GND applied to the (V-) pin. Input signals must stay within the recommended input range for either type. Note that with a "split" supply the output now swings "low" (V_{OL}) to (V-) potential and not GND.

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7.4 Layout

7.4.1 Layout Guidelines

For accurate comparator applications, a stable power supply with minimized noise and glitches is important. Output rise and fall times are in the tens of nanoseconds, and must be treated as high speed logic devices. The bypass capacitor must be as close to the supply pin as possible and connected to a solid ground plane, and preferably directly between the (V+) and GND pins.

Minimize coupling between outputs and inputs to prevent output oscillations. Do not run output and input traces in parallel unless there is a (V+) or GND trace between output to reduce coupling. When series resistance is added to inputs, place resistor close to the device. A low value (<100Ω) resistor can also be added in series with the output to dampen any ringing or reflections on long, non-impedance controlled traces. For best edge shapes, controlled impedance traces with back-terminations can be used when routing long distances.

7.4.2 Layout Example

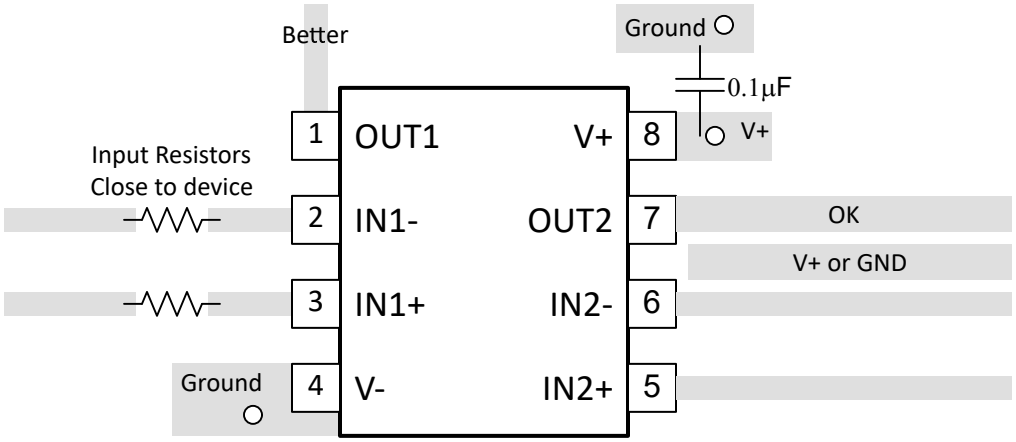


Figure 7-9. Dual Layout Example

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8 Device and Documentation Support

8.1 Documentation Support

8.1.1 Related Documentation

- Texas Instruments, *Analog Engineers Circuit Cookbook: Amplifiers* (See Comparators section) - SLYY137
- Texas Instruments, *Precision Design, Comparator with Hysteresis Reference Design*— TIDU020
- Texas Instruments, *Comparator with and without hysteresis circuit* - SBOA219
- Texas Instruments, *Inverting comparator with hysteresis circuit* - SNOA997
- Texas Instruments, *Non-Inverting Comparator With Hysteresis Circuit* - SBOA313

8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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8.4 Trademarks

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8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (December 2025) to Revision C (September 2026)	Page
• Deleted Preview from TLV3221 (DCK and DBV packages)	1
• Deleted Preview from TLV3222 (DGK package)	1

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLV3211DBVR	Active	Production	SOT-23 (DBV) | 5	3000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	46XF
TLV3211DCKR	Active	Production	SC70 (DCK) | 5	3000 | LARGE T&R	Yes	POST-PLAT AG SPOT	Level-1-260C-UNLIM	-40 to 125	1ZW
TLV3212DGKR	Active	Production	VSSOP (DGK) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	3WOS
TLV3214PWR	Active	Production	TSSOP (PW) | 14	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TLV3214
TLV3221DCKR	Active	Production	SC70 (DCK) | 5	3000 | LARGE T&R	Yes	POST-PLAT AG SPOT	Level-1-260C-UNLIM	-40 to 125	1ZZ
TLV3222DGKR	Active	Production	VSSOP (DGK) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	3WQS

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TLV3211, TLV3212, TLV3214, TLV3221, TLV3222 :

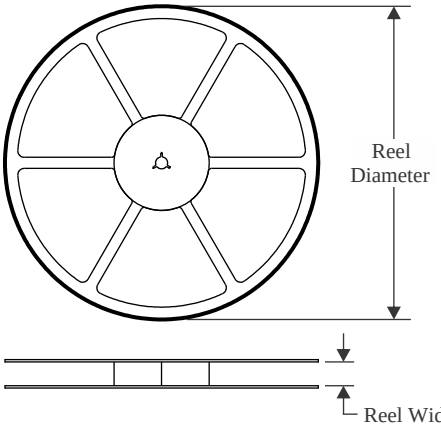
- Automotive : TLV3211-Q1, TLV3212-Q1, TLV3214-Q1, TLV3221-Q1, TLV3222-Q1

NOTE: Qualified Version Definitions:

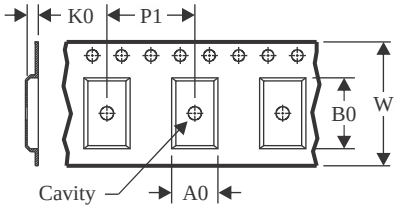
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

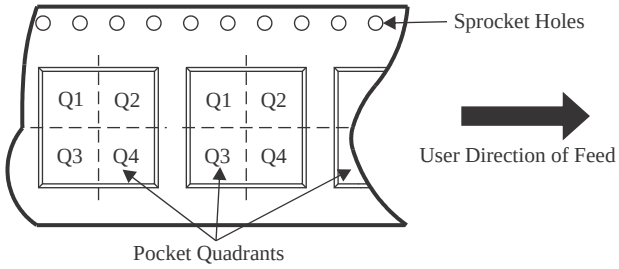


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

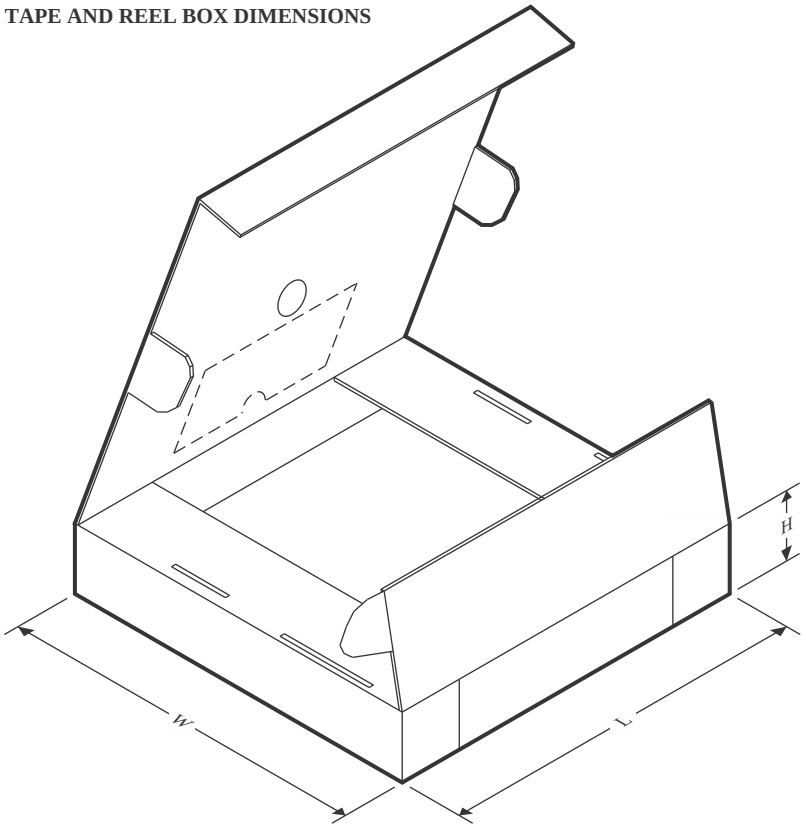
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV3211DCKR	SC70	DCK	5	3000	180.0	8.4	2.3	2.55	1.2	4.0	8.0	Q3
TLV3212DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TLV3214PWR	TSSOP	PW	14	3000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLV3221DCKR	SC70	DCK	5	3000	180.0	8.4	2.3	2.55	1.2	4.0	8.0	Q3
TLV3222DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

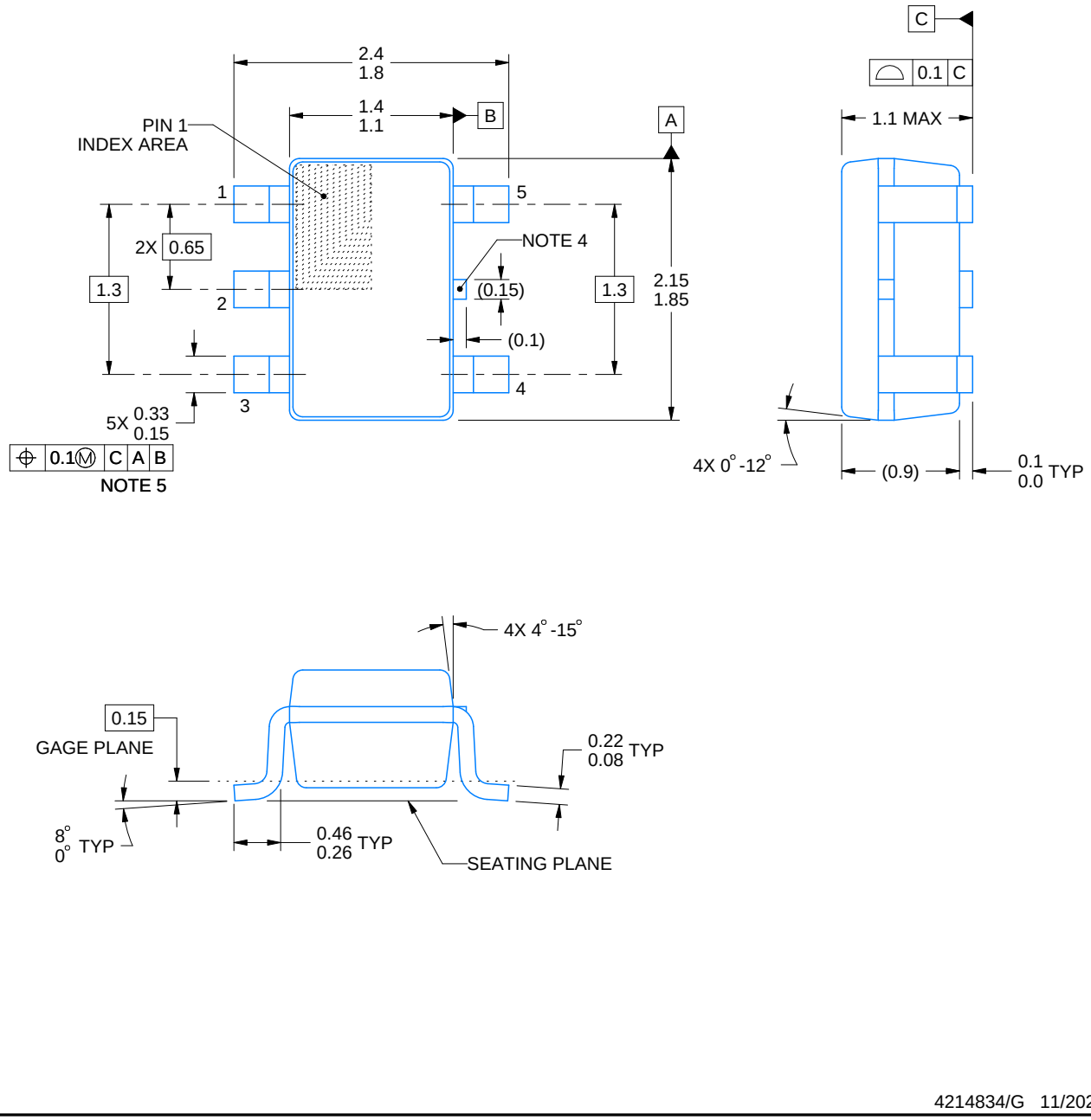
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV3211DCKR	SC70	DCK	5	3000	210.0	185.0	35.0
TLV3212DGKR	VSSOP	DGK	8	2500	353.0	353.0	32.0
TLV3214PWR	TSSOP	PW	14	3000	353.0	353.0	32.0
TLV3221DCKR	SC70	DCK	5	3000	210.0	185.0	35.0
TLV3222DGKR	VSSOP	DGK	8	2500	353.0	353.0	32.0

PACKAGE OUTLINE

DCK0005A

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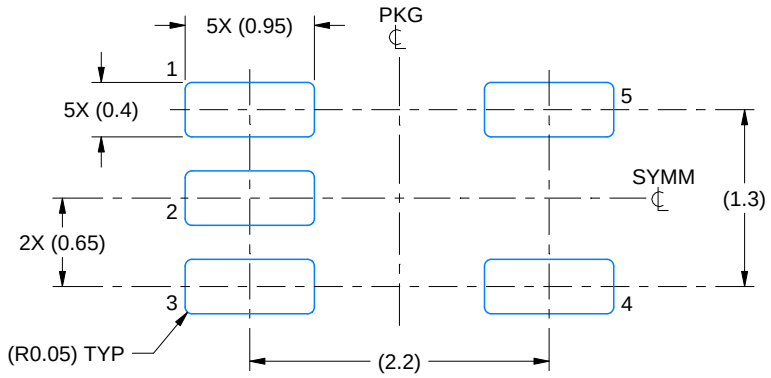
SMALL OUTLINE TRANSISTOR



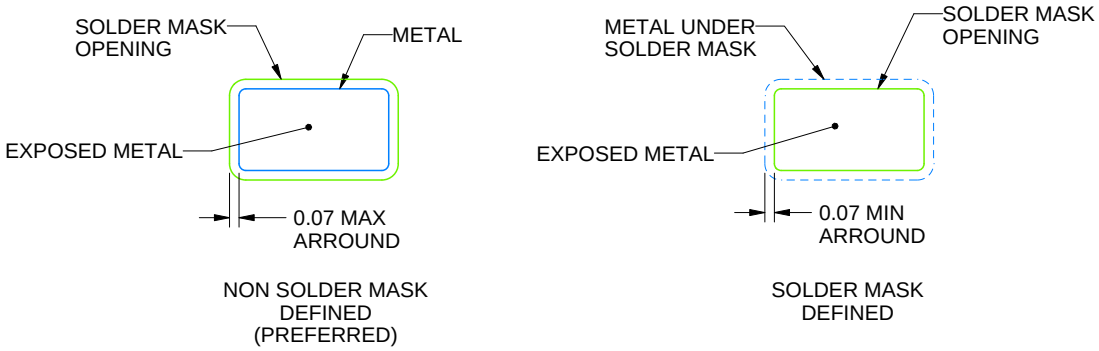
4214834/G 11/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.
6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X

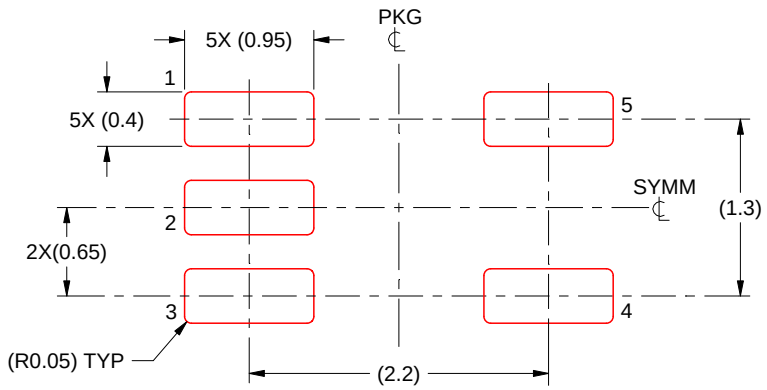


SOLDER MASK DETAILS

4214834/G 11/2024

NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4214834/G 11/2024

NOTES: (continued)

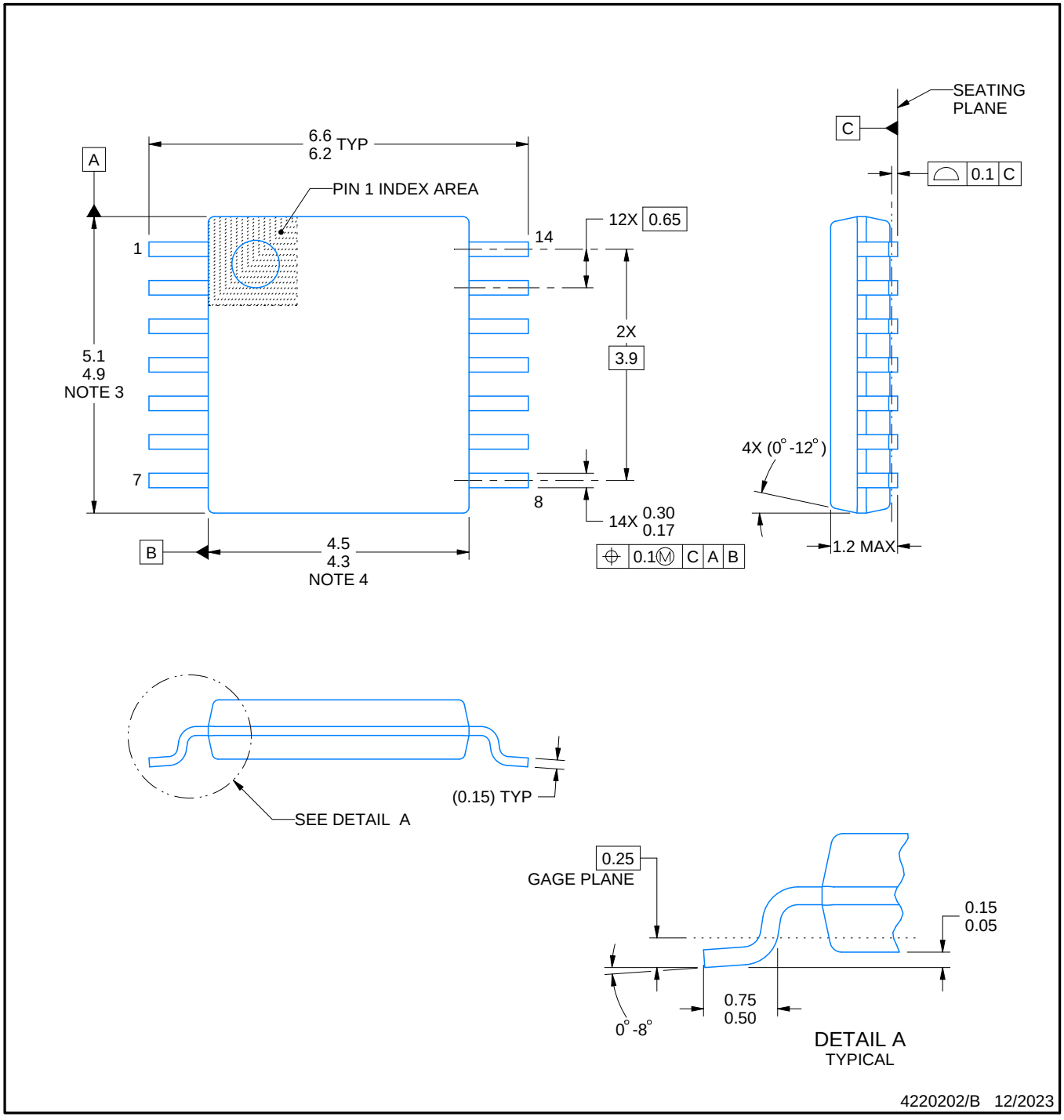
9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

PW0014A

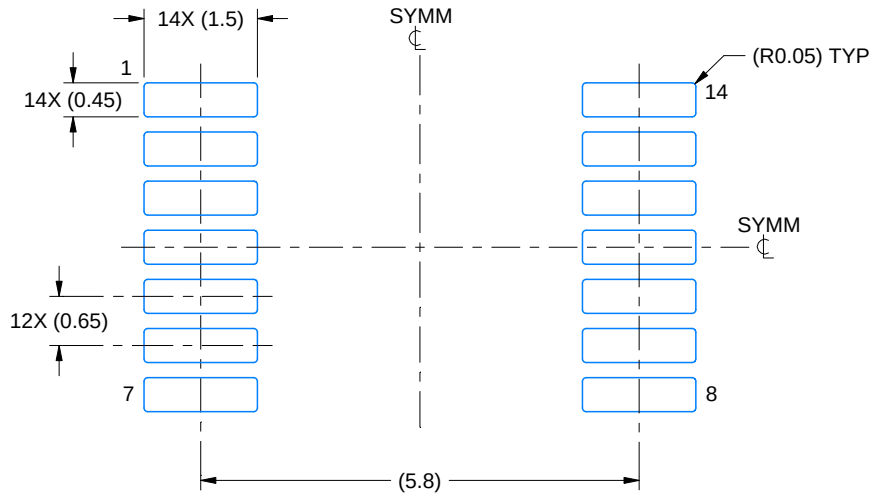
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

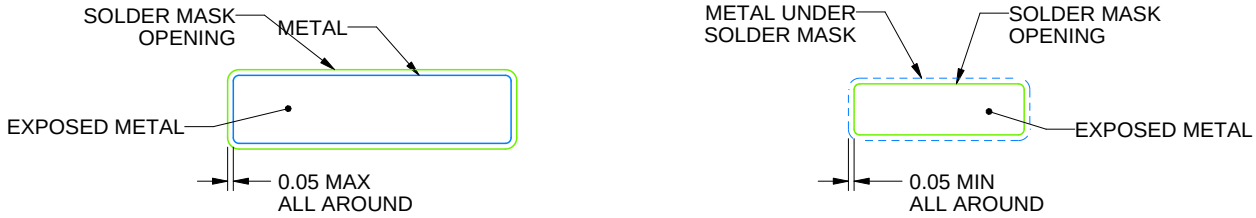


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

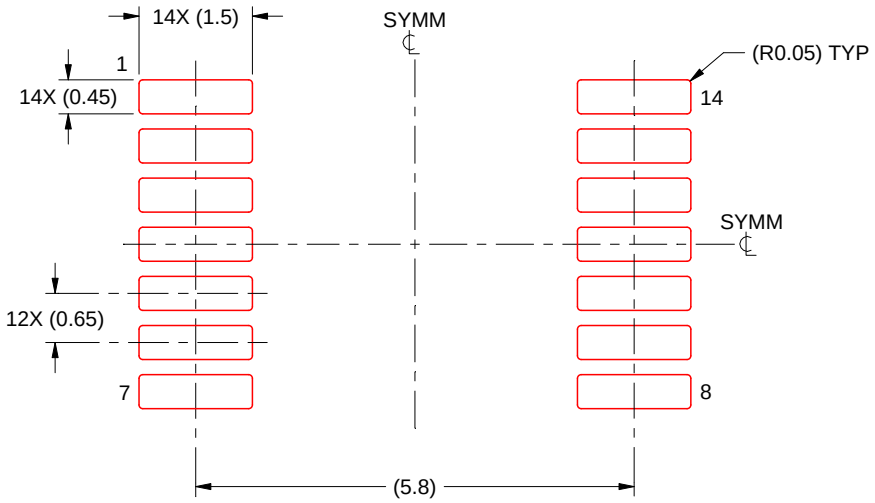


SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

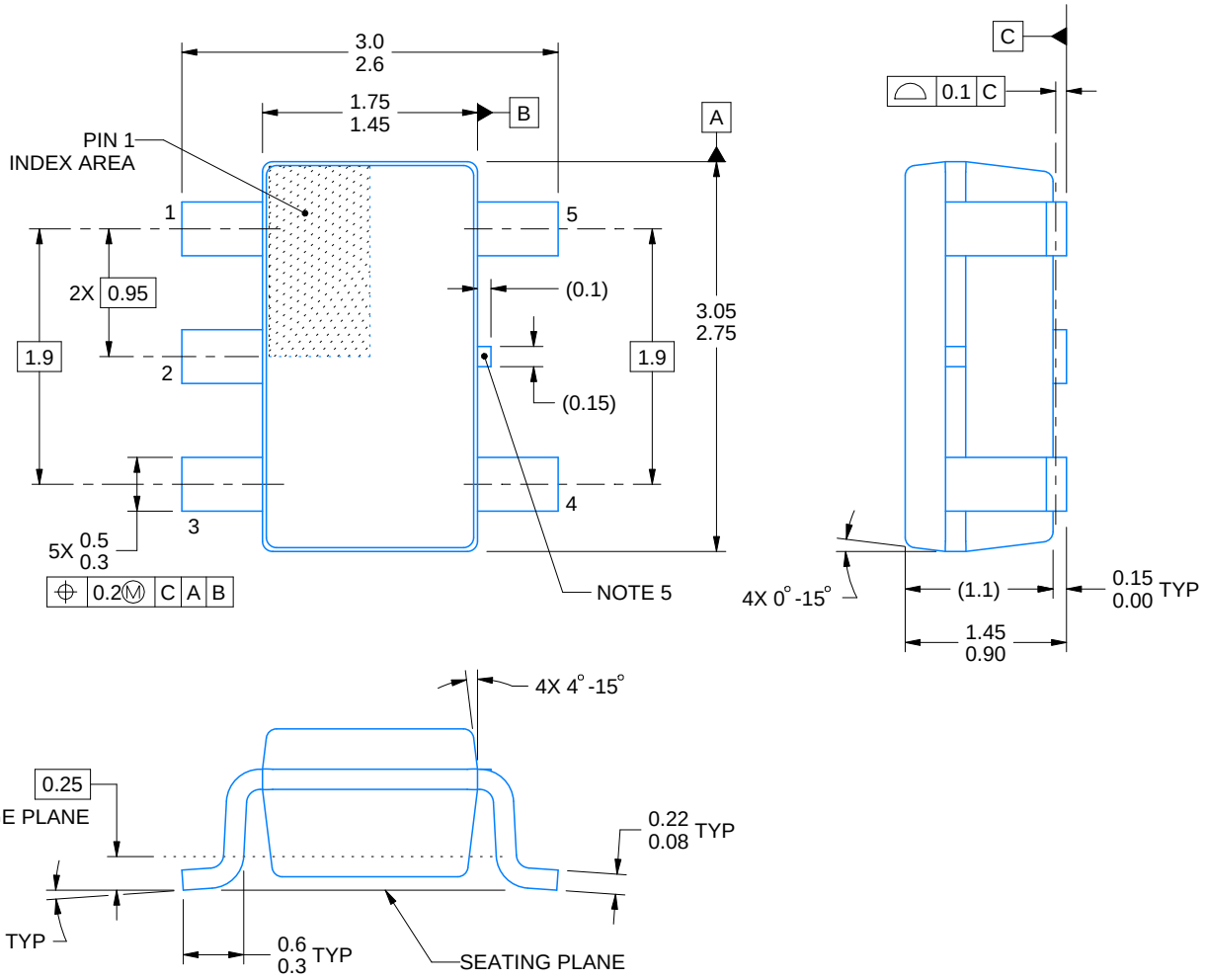
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DBV0005A

SOT-23 - 1.45 mm max height

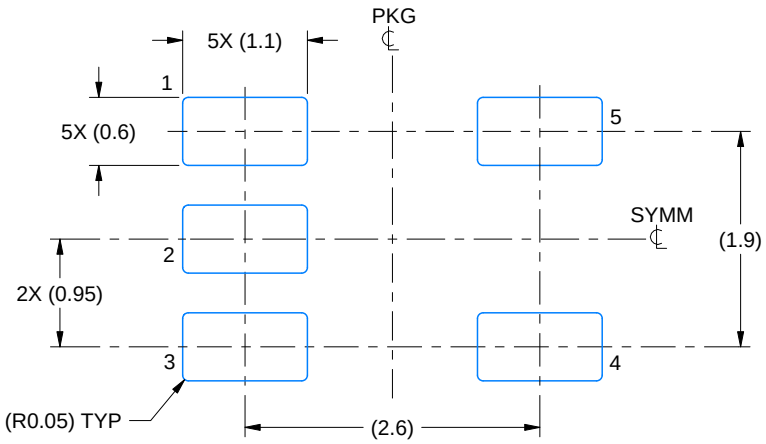
SMALL OUTLINE TRANSISTOR



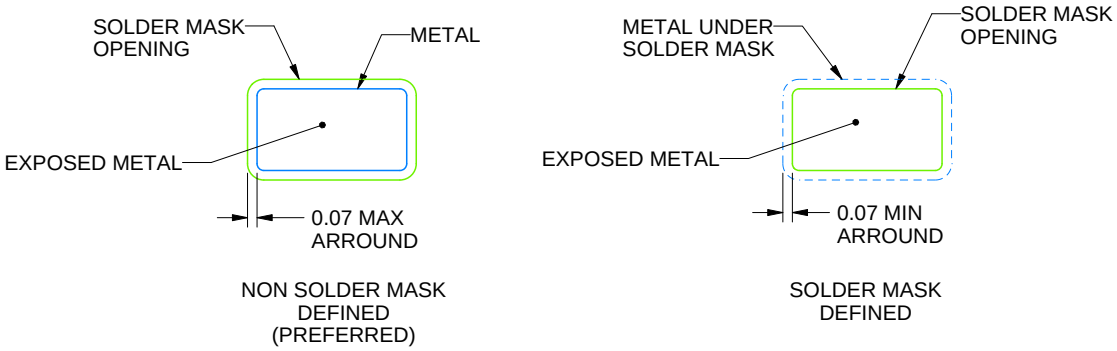
4214839/K 08/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

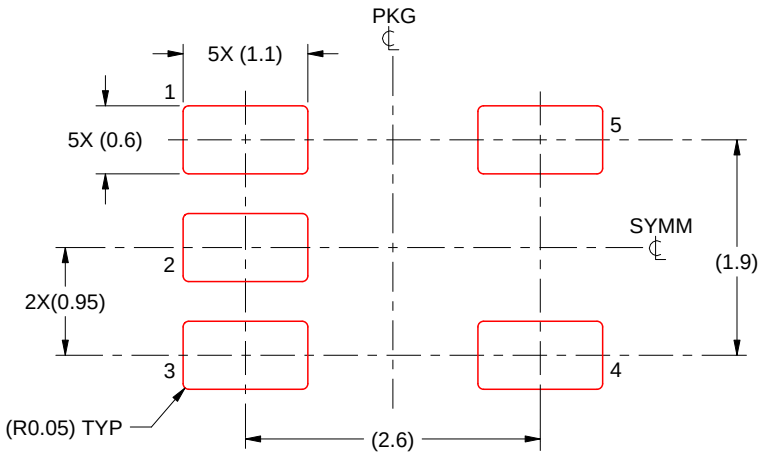


SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

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NOTES: (continued)

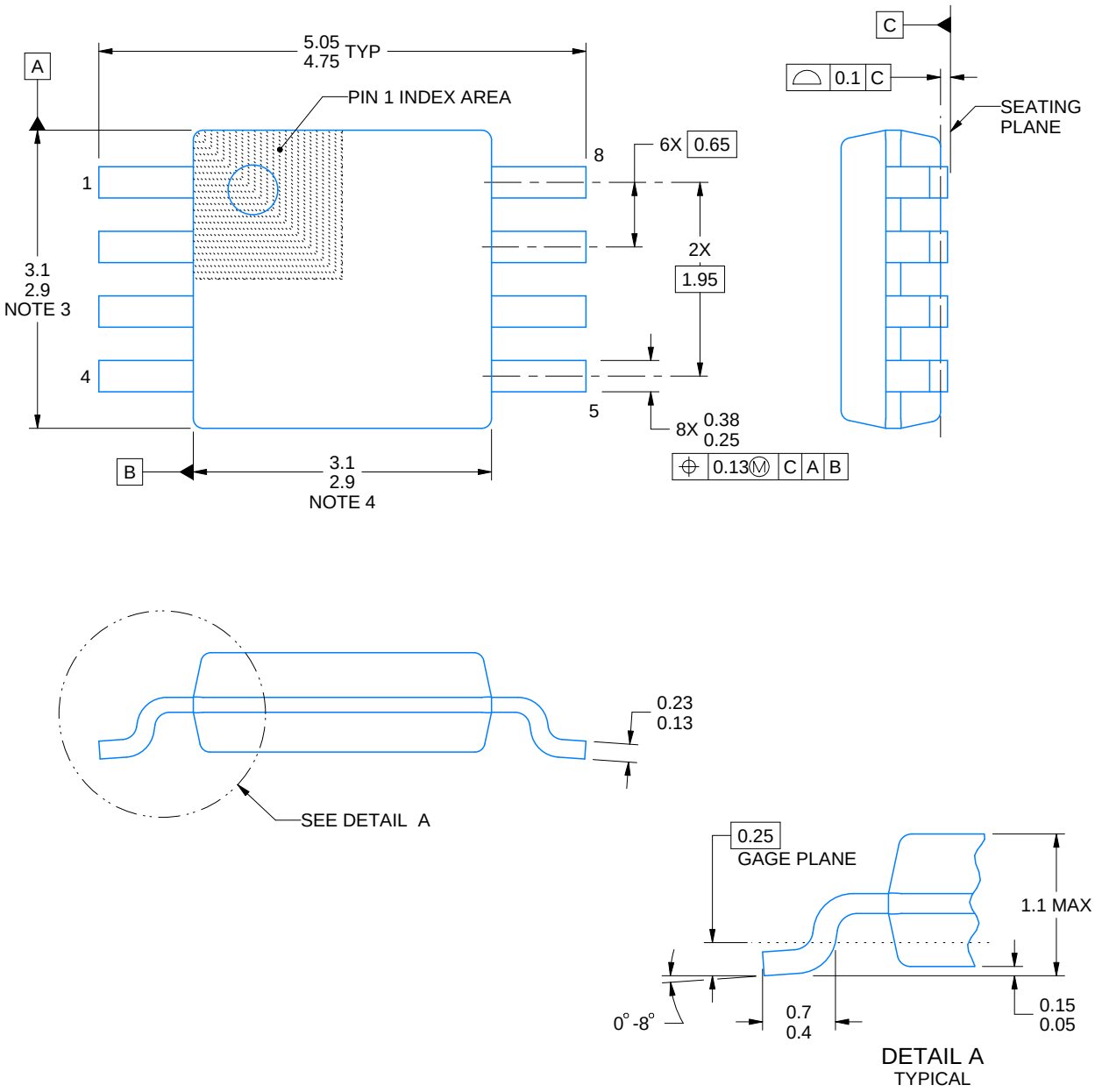
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DGK0008A

VSSOP - 1.1 mm max height

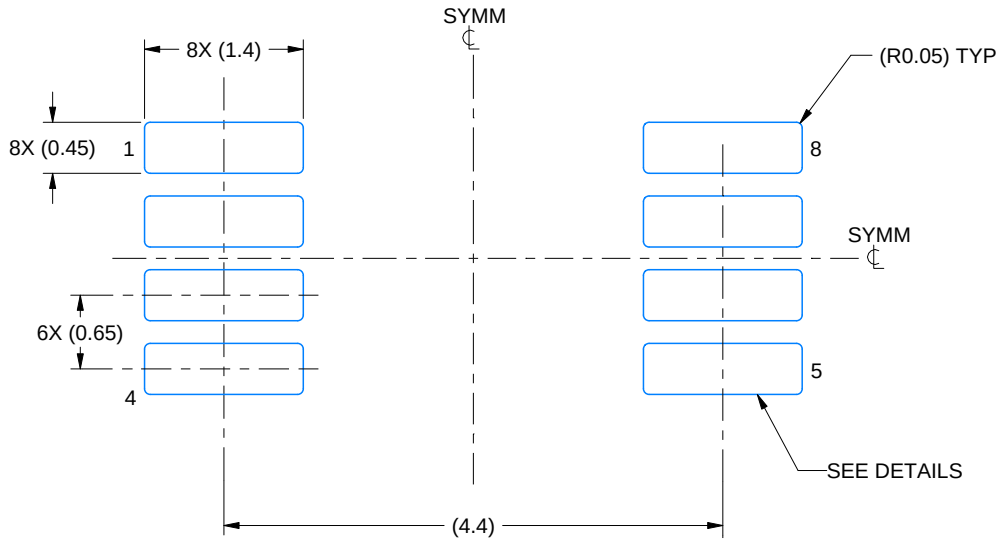
SMALL OUTLINE PACKAGE



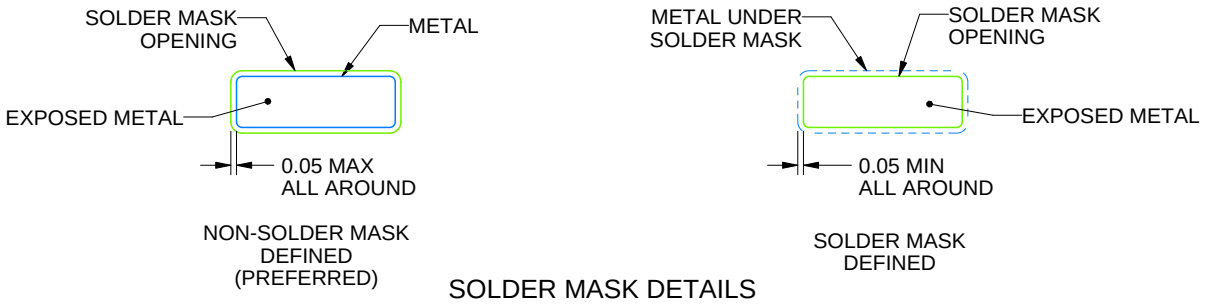
PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X

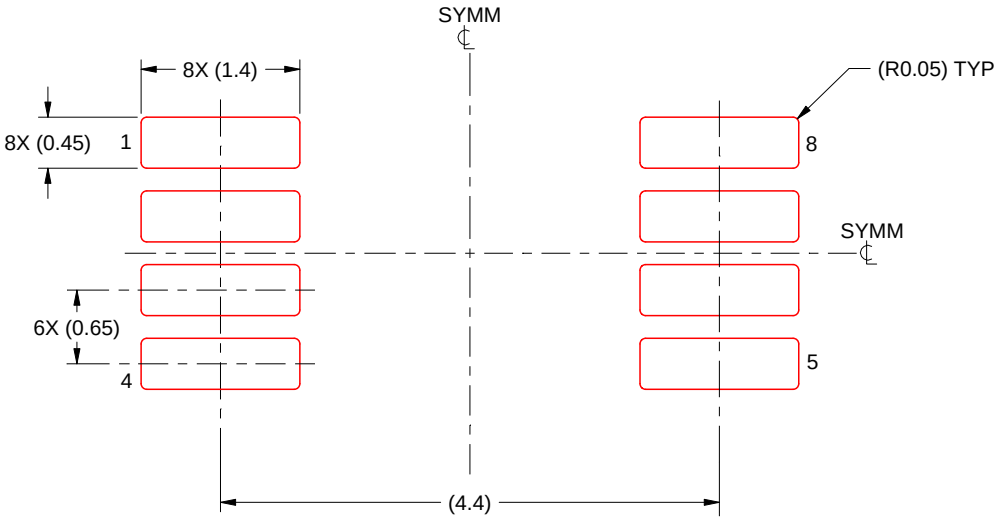


SOLDER MASK DETAILS

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.



SOLDER PASTE EXAMPLE
SCALE: 15X

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NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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